8-bit Microcontroller смоз

F²MC-8L MB89530A Series

MB89535A/537A/537AC/538A/538AC/F538 MB89P538/PV530

DESCRIPTION

The MB89530A series is a one-chip microcontroller featuring the F²MC-8L core supporting low-voltage and highspeed operation. Built-in peripheral functions include timers, serial interface, A/D converter, and external interrupt. This product is an ideal general-purpose one-chip microcontroller for a wide variety of applications from household to industrial equipment, as well as use in portable devices.

Note : F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURES

- Wide range of package options
 - QFP package (1.00 mm pitch)
 - Two types of LQFP packages (0.65 mm pitch, 0.50 mm pitch)
 - SH-DIP package (1.778 mm pitch)
 - BCC package (0.50 mm pitch)
- Low voltage, high-speed operating capability Minimum instruction execution time 0.32 μs (at base oscillator 12.5 MHz)
- F²MC-8L CPU Core
 - Instruction set optimized for controller operation
 - Multiplication/division instructions
 - 16-bit calculation
 - Branching instructions with bit testing
 - Bit operation instructions, etc.



(Continued)

- Five timer systems
 - 8-bit PWM timer with 2 channels (usable as either interval timer of PWM timer)
 - Pulse width count timer (supports continuous measurement or remote control receiving applications)
 - 16-bit timer counter
 - 21-bit time base timer
 - Watch prescaler (17-bit)
- UART

Synchronous or asynchronous operation, switchable

- 2 serial interfaces (Serial I/O)
 - Selection of transfer direction (specify MSB first or LSB first) for communication with a variety of devices
- 10-bit A/D converter (8 channels)
 - External clock input for startup support
 - Time base timer output for startup support (except MB89F538)
- Pulse generators (PPG) with 2-program capability
 - 6-bit PPG with selection of pulse width and pulse period
 - 12-bit PPG (2 channels) with selection of pulse width and pulse period
- I²C* interface circuits
- External interrupt 1 (single-clock system : 4 channels, dual-clock system : 3 channels)
 4 or 3 independent inputs, release enabled from standby mode (includes edge detection function)
- External interrupt 2 (except for MB89F538 : 8 channels, MB89F538 : 7 channels)
- 8 or 7 independent input, release enabled form standby mode (includes level edge detection function)
- Standby modes (low power consumption modes)
 - Stop mode (oscillator stops, virtually no power consumed)
 - Sleep mode (CPU stops, power consumption reduced to one-third)
 - Sub clock mode
 - Watch mode
- Watchdog timer reset
- I/O ports
 - Maximum ports

Single-clock system : Except MB89F538 53 ports

-	•	•
	: MB89F538	52 ports

Dual-clock system : Except MB89F538 51 ports

: MB89F538 50 ports

- 38 general-purpose I/O ports (CMOS) (MB89F538 : 37 general-purpose I/O ports)
- 2 general-purpose I/O ports (N-ch open drain)
- 8 general-purpose output ports (N-ch open drain)
- General-purpose input ports (CMOS) : single-clock system : 5 ports, dual-clock system : 3 ports
- * : Purchase of Fujitsu I²C components conveys a license under the Philips I²C Patent Rights to use, these components in an I²C system provided that the system conforms to the I²C Standard Specification as defined by Philips.

■ PRODUCT LINEUP

	Part number								
Pa	rameter	MB89535A	MB89537A/ 537AC	MB89538A/ 538AC	MB89F538	MB89P538	MB89PV530		
Ту	pe	Mass produced (MASK ROM) Flash product One-time Eva programmable product product							
ROM capacity		16 Kbytes× 8-bit (built-in ROM)	32 Kbytes × 8-bit (built-in ROM)	48 Kbytes × 8-bit (built-in ROM)	8-bit (built-in Flash) (built-in (write from		48 Kbytes × 8-bit (external ROM) *2		
RA	M capacity	512 bytes × 8-bit	1 Kbyte × 8-bit		2 Kby	rtes $ imes$ 8-bit			
	perating Itage		2.2 V to 5.5 V 537A/538A/53		3.5 V to 5.5 V	2.7 V to 5.5 V	2.7 V to 5.5 V		
CPU functions Basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 bit to 3 bits Data bit length : 1, 8, 16 bits Minimum instruction execution time : 0.32 µs / 12.5 MHz Minimum interrupt processing time : 2.88 µs / 12.5 MHz									
pheral functions	Ports	Input ports : single-clock system : 5 (4 also usable as external interrupts) dual-clock system Output-only ports (N-ch open drain) : 8 (8 also usable as A/D converter input) I/O ports (N-ch open drain) : 2 (2 also usable as SO2/SDA or SI2/SCL) I/O ports (CMOS) (Except MB89F538) : 38 I/O ports (CMOS) (MB89F538) : 37 (21 have no other function) Total (except MB89F538) : single-clock system : 53 dual-clock system : 51 Total (MB89F538) : single-clock system : 50							
Peripher	Time base timer		ods at main c 55 ms, 2.621		n frequency of 12. , 335.5 ms)	5 MHz			
	Watchdog timer				5.6 ms at main cloo ms at sub clock fr				
	PWM timer	8-bit interval timer operation (supports square wave output, operating clock period : 1, 8, 16, 64 tinst*3)							
Wa	Vatch prescaler Interval times at 17-bit sub clock base frequency of 32.768 kHz (approx. 31.25 ms, 0.25 s, 0.50 s, 1.00 s, 2.00 s, 4.00 s)								

(Continued)

(Continued) Part numbe		MB89537A/	MB89538A/	MB89F538								
Parameter	MB89535A	MB89P538	MB89PV530									
Pulse width count timer	(supports unde 8-bit reload tim (supports squa 8-bit pulse widt (continuous me	 8-bit one-shot timer operation (supports underflow output, operating clock period : 1, 4, 32 t_{inst}*³, external) 8-bit reload timer operation (supports square wave output, operating clock period : 1, 4, 32 t_{inst}*³, external) 8-bit pulse width measurement operation (continuous measurement, "H" width measurement, "L" width measurement, ↑ to ↑, ↓ to ↓ width measurement and ↑ to↑) 										
16-bit timer/ counter		eration (operatin unter operation nel										
Serial I/O		B first or MSB f (2, 8, 32 t _{inst} *3, e										
UART/SIO	without parity b	ous/CLK asynch pit) . ute generator pro				ity bit, or 7,8-bit						
	7, 8, 9-bit with Built-in baud ra	CLK synchronous/CLK asynchronous data transfer capability (4, 6, 7, 8-bit with parity bit, or 5, 7, 8, 9-bit without parity bit). Built-in baud rate generator provides selection of 14 baud rate settings. External clock output, 2-channel 8-bit PWM timer output also available for baud rate										
External interrupt 1	Selection of ris	stem : 4 channe ing, falling, or bo or recovery from	oth edge detecti	on.								
External interrupt 2		538 : 8 channels or recovery from		7 channels								
6-bit PPG, 12-bit PPG		square wave sig el or 12-bit \times 2 c		ammable period								
I ² C bus interface	_	 1-channel , compatible with Intel System Administrator bus version 1.0 and Philips I²C specifications. 2-line communications (on MB89PV530/P538/F538/537AC/538AC) 										
A/D converter	A/D conversion Supports repea Supports repea	10-bit resolution × 8 channels. A/D conversion functions (conversion time : 60 t _{inst} * ³) Supports repeated calls from external clock (except MB89F538) . Supports repeated calls from internal clock. Standard voltage input provided (AVR)										
Standby modes (power saving modes)	Sleep mode, stop mode, sub clock mode, watch mode.											
Process	CMOS											

*1 : Depends on operating frequency.

*2 : Using external ROM and MBM27C512.

- *3 : tinst represents instruction execution time. This can be selected as 1/4, 1/8, 1/16, 1/64 of the main clock cycle or 1/2 of the sub clock cycle.
- Note : MB89535A/537A/538A have no built-in I²C functions.

To use I²C functions, choose the MB89PV530/MB89P538/F538/537AC/538AC.

MODEL DIFFERENCES AND SELECTION CONSIDERATIONS

Part number Package	MB89535A	MB89537A/ 537AC	MB89538A/ 538AC	MB89F538	MB89P538	MB89PV530
DIP-64P-M01	0	0	0	0	0	×
FPT-64P-M03	0	0	0	×	×	×
FPT-64P-M06	0	0	0	0	0	×
FPT-64P-M09	0	0	0	0	0	×
LCC-64P-M19	0	0	0	Х	X	×
LCC-64P-M16	×	×	×	×	○ *	×
MDP-64C-P02	Х	Х	Х	Х	Х	0
MQP-64C-P01	×	×	×	×	×	0

 \bigcirc : Model-package combination available

imes : Model-package combination not available

* : Only for ES

Conversion sockets for pin pitch conversion (manufactured by Sunhayato Corp.) can be used.

Contact : Sunhayato Corp. :

TEL :+81-3-3984-7791 FAX

:+81-3-3971-0535

Advanced Interconnectics : http://www.advantest.co.jp/en-index.shtml

DIFFERENCES AMONG PRODUCTS

1. Memory Capacity

When this product is used in an evaluation product or other evaluation configuration, it is necessary to carefully confirm the differences between the model being used and the product it is evaluating. Particular attention should be given to the following (Refer to "■CPU CORE 1.Memory Space").

- The program ROM area starts from address 4000H on the MB89F538, MB89P538 and MB89PV530 models.
- Note upper limits on RAM, such as stack areas, etc.

2. Current Consumption

- On the MB89PV530, the additional current consumed by the EPROM is added at the connecting socket on the back side.
- When operating at low speed, the current consumption in the one-time PROM or EPROM models is greater than on the MASK ROM models. However, current consumption in sleep or stop modes is identical.

For details, refer to "ELECTRICAL CHARACTERISTICS".

3. Mask Options

The options available for use, and the method of specifying options, differ according to the model. Before use, check the "MASK OPTIONS" specification section.

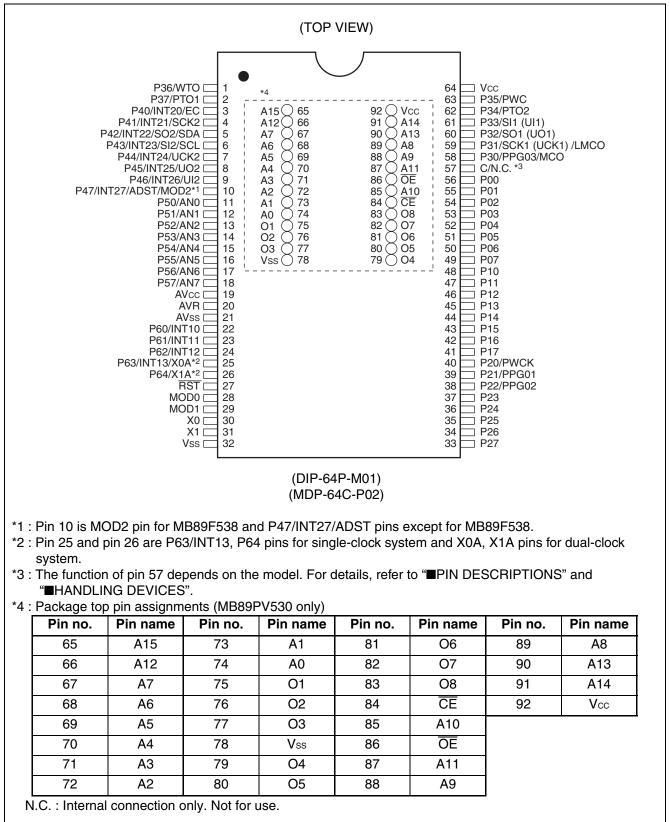
4. Wild Register Functions

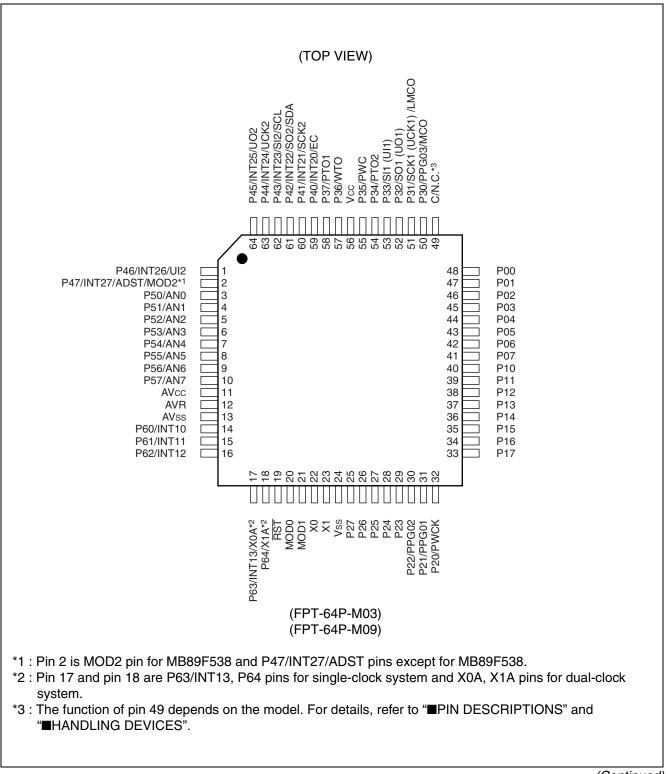
The following table shows areas in which wild register functions can be used.

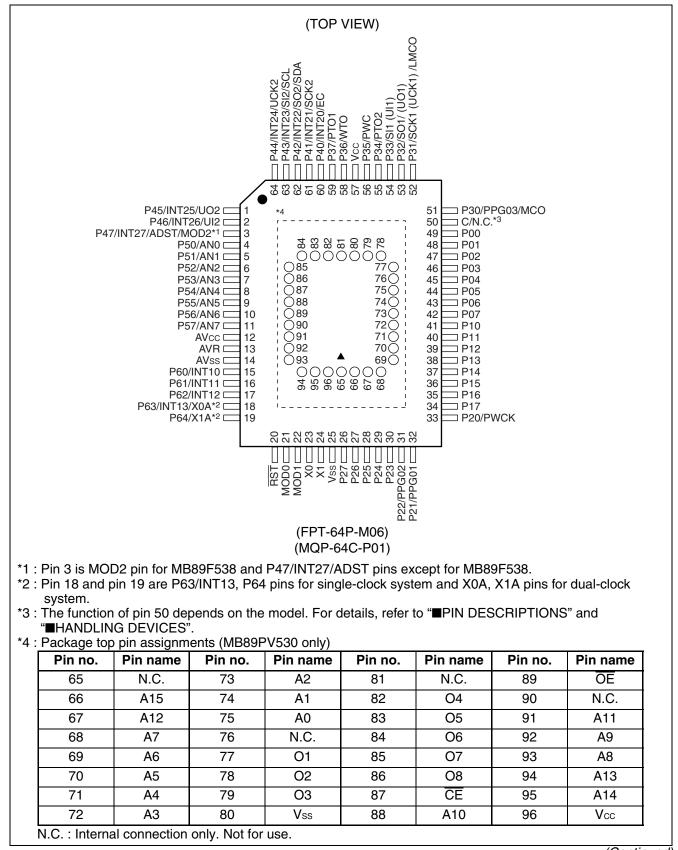
Wild Register Usage Areas

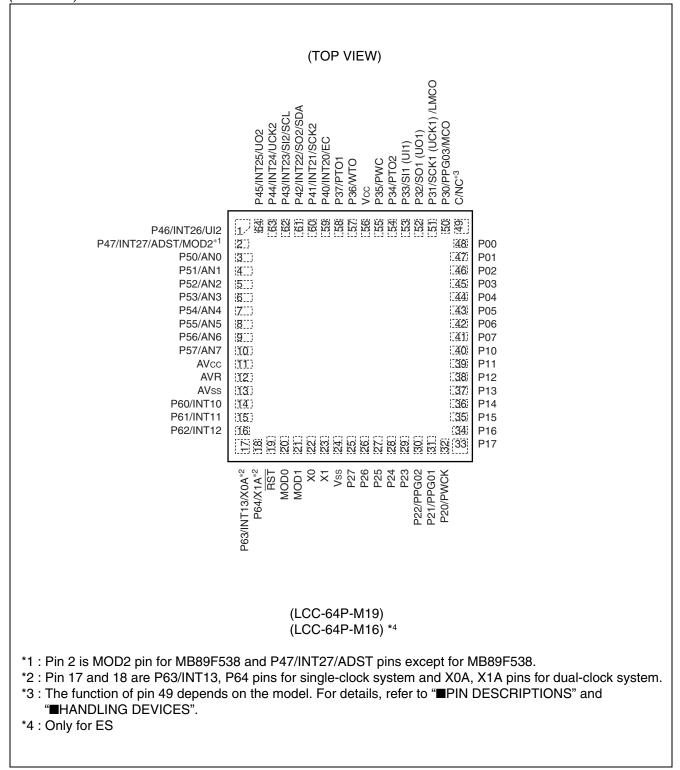
Part number	Address space
MB89PV530	4000н to FFFFн
MB89P538	4000н to FFFFн
MB89F538	4000н to FFFFн
MB89537A/537AC	8000н to FFFFh
MB89538A/538AC	4000н to FFFFн
MB89535A	C000н to FFFFн

■ PIN ASSIGNMENTS









■ PIN DESCRIPTIONS

Pin no.				I/O	
SH-DIP ^{*1} MDIP ^{*2}	QFP ^{*3} MQFP ^{*4}	LQFP*5 BCC*6	Pin name	circuit type* ⁷	Function
30	23	22	X0		Connecting pins to crystal oscillator circuit or other
31	24	23	X1	A	oscillator circuit. The X0 pin can connect to an external clock. In that case, X1 is left open.
28	21	20	MOD0	В	Input pins for memory access mode setting.
29	22	21	MOD1		Connect directly to Vss.
27	20	19	RST	С	Reset I/O pin. This pin has pull-up resistance with CMOS I/O or hysteresis input. At an internal reset request, an 'L' signal is output. An 'L' level input initializes the internal circuits.
56 to 49	49 to 42	48 to 41	P00 to P07	D	General purpose I/O ports.
48 to 41	41 to 34	40 to 33	P10 to P17	D	General purpose I/O ports.
40	33	32	P20/PWCK	Е	General purpose I/O port.Resource I/O pin (hysteresis input).Hysteresis input. This pin also functions as a PWC input.
39	32	31	P21/ PPG01	D	General purpose I/O port. This pin also functions as the PPG01 output.
38	31	30	P22/ PPG02	D General purpose I/O port. This pin also function PPG02 output.	
37	30	29	P23	D	General purpose I/O port.
36	29	28	P24	D	General purpose I/O port.
35	28	27	P25	D	General purpose I/O port.
34	27	26	P26	D	General purpose I/O port.
33	26	25	P27	D	General purpose I/O port.
58	51	50	P30/ PPG03/ MCO	D	General purpose I/O port.This pin also functions as the PPG03 output.
59	52	51	P31/SCK1 (UCK1) / LMCO	E	General purpose I/O port.Resource I/O pin (hysteresis input).This pin also functions as the UART/SIO clock input/output pin.
60	53	52	P32/SO1 (UO1)	D General purpose I/O port.This pin also functions UART/SIO data output pin.	
61	54	53	P33/SI1 (UI1)	E General purpose I/O port.Resource input/output (hysteresis input).This pin also functions as the U SIO serial data input pin.	
62	55	54	P34/PTO2	D	General purpose I/O port.This pin also functions as the PWM timer 2 output pin.
63	56	55	P35/PWC	Е	General purpose I/O port.Resource I/O pin (hysteresis input).This pin also functions as a PWC input.

Pin no.		Pin I/O			
SH-DIP*1 MDIP*2	QFP ^{*3} MQFP ^{*4}	LQFP*5 BCC*6	Pin name	circuit type* ⁷	Function
1	58	57	P36/ WTO	D	General purpose I/O port.Resource output. This pin also functions as the PWC output pin.
2	59	58	P37/ PTO1	D	General purpose I/O port.Resource output. This pin also functions as the PWM timer 1 output pin.
3	60	59	P40/ INT20/ EC	Е	General purpose I/O port.Resource I/O pin (hysteresis input).This pin also functions as an external interrupt input or 16-bit timer/counter input.
4	61	60	P41/ INT21/ SCK2	Е	General purpose I/O port.Resource I/O pin (hysteresis input).This pin also functions as an external interrupt input or SIO clock I/O pin.
5	62	61	P42/ INT22/ SO2/ SDA	G	N-ch open drain output. Resource I/O pin (hysteresis only for INT22 input) . This pin also functions as an external interrupt input, SIO serial data output, or I ² C data line.
6	63	62	P43/ INT23/ SI2/SCL	G	N-ch open drain output. Resource I/O pin (hysteresis only for INT23 input) . This pin also functions as an external interrupt, SIO serial data input, or I ² C clock I/O pin.
7	64	63	P44/ INT24/ UCK2	Е	General purpose I/O port. Resource I/O pin (hysteresis input) . This pin also functions as an external interrupt input or UART clock I/O pin.
8	1	64	P45/ INT25/ UO2	Е	General purpose I/O port. Resource I/O pin (hysteresis input) . This pin also functions as an external interrupt input or UART data output pin.
9	2	1	P46/ INT26/ UI2	Е	General purpose I/O port. Resource I/O pin (hysteresis input) . This pin also functions as an external interrupt input or UART data input pin.
10	3	2	P47/ INT27/ ADST	E	Except MB89F538 General purpose I/O port. Resource I/O pin (hysteresis input) . This pin also functions as an external interrupt input or
			MOD2	В	A/D converter clock input pin. MB89F538 Input pins for memory access mode setting. Connect directly to Vss.
11 to 18	4 to 11	3 to 10	P50/AN0 to P57/ AN7	Н	N-ch open drain output port. This pin also functions as an A/D converter analog input pin.

(Continued)

Pin no.			I/O					
SH-DIP*1 MDIP*2	QFP* ³ MQFP ^{*4}	LQFP*5 BCC*6	Pin name	circuit type* ⁷	Function			
22 to 24	15 to 17	14 to 16	P60/INT10 to P62/INT12	I	General purpose input p Resource input pin (hyst This pin also functions as			
25	18	17	P63/INT13 I		Single-clock system	General purpose input port. Resource input (hysteresis input) . This pin also functions as an external interrupt.		
			X0A	Α	Dual-clock system	Connected pin for sub clock.		
26	19	18	P64	J	Single-clock system	General purpose input port.		
20	10	10	X1A	Α	Dual-clock system	Connected pin for sub clock.		
64	57	56	Vcc	—	Power supply pin.			
32	25	24	Vss		Ground pin (GND) .			
19	12	11	AVcc		A/D converter power supply pin.			
20	13	12	AVR		A/D converter reference voltage input pin.			
21	14	13	AVss	_	A/D converter power supply pin. Used at the same voltage level as the Vss supply.			
	MB89F538		MB89F538	Capacitor connection pin for stabilization power supply. Connect an external ceramic capacitor of approximately 0.1 µF.				
57	50	50 49	С		MB89P538	If "Available" is selected for the step-down circuit stabilization time, Vcc is fixed. If "Unavailable" is selected for the step-down circuit stabilization time, Vss is fixed.		
					MB89PV530 MB89537A/537AC MB89538A/538AC MB89535A	N.C. pin		

*1 : DIP-64P-M01

*2 : MDP-64C-P02

*3 : FPT-64P-M06

*4 : MQP-64C-P01

*5 : FPT-64P-M03/M09

*6 : LCC-64P-M19/M16

*7 : For I/O circuit type, refer to " I/O CIRCUIT TYPE".

Pin no.			I/O Circuit	Function					
MDIP*1	MQFP* ²	Pin name	type*3	Function					
65	66	A15							
66	67	A12							
67	68	A7							
68	69	A6							
69	70	A5	0	Address output pins.					
70	71	A4	-						
71	72	A3							
72 73	73 74	A2							
73	74 75	A1 A0							
75	77	01							
76	78	O2	I	Data input pins					
77	79	O3							
78	80	Vss	0	Power supply pin (GND) .					
79	82	O4							
80	83	O5		Data input pins.					
81	84	O6	I						
82	85	07							
83	86	O8							
84	87	CE	О	ROM chip enable pin. Outputs an "H" level signal in standby mode.					
85	88	A10	0	Address output pin.					
				ROM output enable pin.					
86	89	OE	0	Outputs "L" at all times.					
87	91	A11		,					
88	91	ATT A9	0						
89	93	A8	Ŭ						
90	94	A13	0	Address output pins.					
91	95	A14	0						
92	96	Vcc	0	EPROM power supply pin.					
	65 76 81 90	N.C.	0	Internally connected. These pins always left open.					

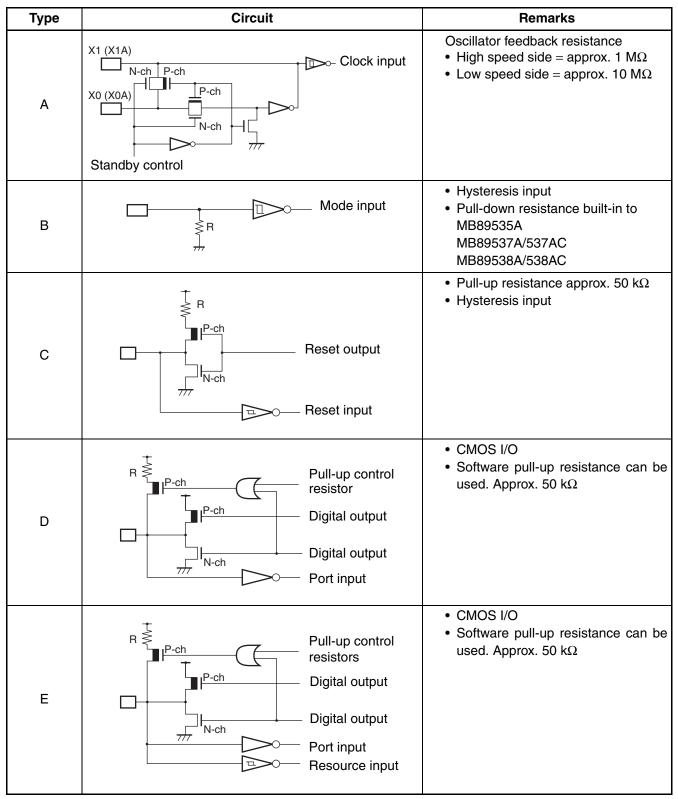
External EPROM Socket Pin Function Descriptions (MB89PV530 only)

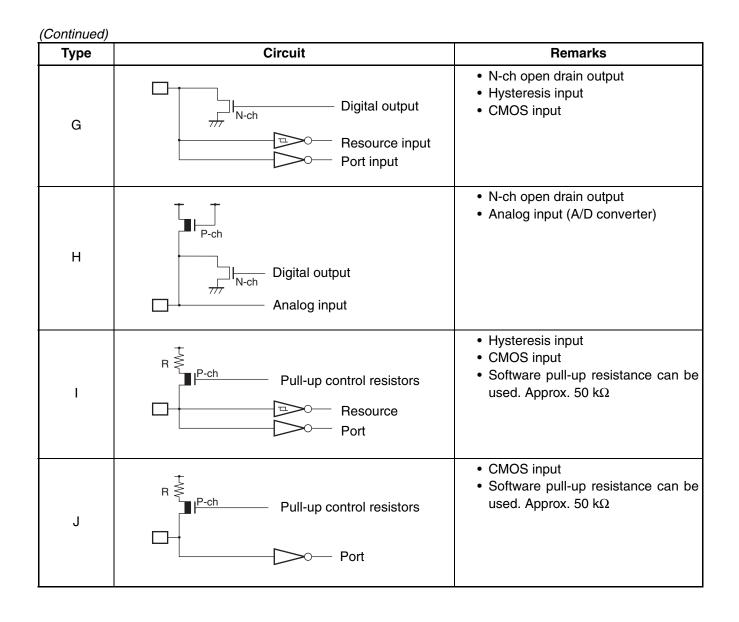
*1 : MDP-64C-P02

*2 : MQP-64C-P01

*3 : For I/O circuit type, refer to "

■ I/O CIRCUIT TYPES





■ HANDLING DEVICES

1. Preventing Latch-up

Care must be taken to ensure that maximum voltage ratings are not exceeded (to prevent latch-up). When CMOS integrated circuit devices are subjected to applied voltages higher than Vcc at input and output pins (other than medium- and high-withstand voltage pins), or to voltages lower than Vss, as well as when voltages in excess of rated levels are applied between Vcc and Vss, the phenomenon known as latch-up can occur.

When a latch-up condition occurs, supply current can increase dramatically and may destroy semiconductor elements. In using semiconductor devices, always take sufficient care to avoid exceeding maximum ratings.

Also when switching power on or off to analog systems, care must be taken that analog power supplies (AVcc, AVR) and analog input signals do not exceed the level of the digital power supply.

2. Power Supply Voltage Fluctuations

Even within the warranted operating range of the Vcc supply voltage, sudden changes in supply voltage can cause abnormal operation. As a measure for stability, it is recommended that the Vcc ripple fluctuation (peak to peak value) should be kept within 10% of the reference Vcc value on commercial power supply (50 Hz/60 Hz), and instantaneous voltage fluctuations such as at power-on and shutdown should be kept within a transient variability limit of 0.1V/ms.

3. Treatment of Unused Input Pins

If unused input pins are left open, abnormal operation may result. Any unused input pins should be connected to pull-up or pull-down resistance.

4. Treatment of N.C. Pins

Any pins marked 'NC' (not connected) must be left open.

5. Treatment of Power Supply Pins on Models with Built-in A/D Converter

Even when A/D converters are not in use, pins should be connected so that AVcc = Vcc, and AVss = AVR = Vss.

6. Precautions for Use of External Clock

Even when an external clock signal is used, an oscillator stabilization wait period is used after a power-on reset, or escape from sub clock mode or stop mode.

7. Execution of Programs on RAM

Debugging of programs executed on RAM cannot be performed even when using the MB89PV530.

8. Wild Register Functions

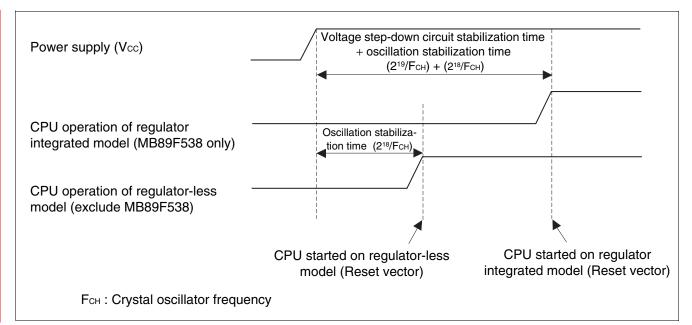
Wild registers cannot be debugged with the MB89PV530 and tools. To verify operations, actual in-device testing on the MB89P538 or MB89F538 is advised.

9. Details on handling the C terminal of the MB89530 series

The MB89530 series contains the following products. The regulator integrated model and the regulator-less model have different performance characteristics.

Part No.	Operation Voltage	integrated model	Terminal type	Terminal treatments	
MB89PV530		Not included	N.C. terminal	Not required	
MB89P538	2.7 V to 5.5 V	Included		Fixed to Vcc	
MIDO9F 550		Not included	C terminal	Fixed to Vss	
MB89F538	3.5 V to 5.5 V	Included		0.1 μF capacitor connected	
MB89537A/537AC					
MB89538A/538AC	2.2 V to 5.5 V	Not included	N.C. terminal	Not required	
MB89535A					

Although these product models have the same internal resources, the operation sequence after a power-on reset is different between the regulator integrated model and regulator-less model. The operation sequence after a power-on reset of each model is shown below.



As above, the regulator integrated model starts the CPU behind the regulator-less model. This is because the regulator requires a settling time for normal operation.

The MB89P538 offers a choice of regulator-integrated and regulator-less models selectable depending on the C-terminal treatment. Use the right one for your mask board.

10. Note to Noise in the External Reset Pin (RST)

If the reset pulse applied to the external reset pin (\overline{RST}) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin (\overline{RST}).

■ PROGRAMMING AND ERASING FLASH MEMORY ON THE MB89F538

1. Flash Memory

The flash memory is located between 4000_{H} and FFFF_H in the CPU memory map and incorporates a flash memory interface circuit that allows read access and program access from the CPU to be performed in the same way as MASK ROM. Programming and erasing flash memory is also performed via the flash memory interface circuit by executing instructions in the CPU. This enables the flash memory to be updated in place under the control of the CPU, providing an efficient method of updating program and data.

2. Flash Memory Features

- 48 Kbytes × 8-bit configuration (16 Kbytes + 8 Kbytes + 8 Kbytes + 16 Kbytes sectors)
- Automatic programming algorithm (Embedded algorithm* : Equivalent to MBM29LV200)
- · Includes an erase pause and restart function
- Data polling and toggle bit for detection of program/erase completion
- · Detection of program/erase completion via CPU interrupt
- · Compatible with JEDEC-standard commands
- · Sector Protection (sectors can be combined in any combination)
- No. of program/erase cycles : 10,000 (Min)
- *: Embedded Algorithm is a trademark of Advanced Micro Devices, Inc.

3. Procedure for Programming and Erasing Flash Memory

Programming and reading flash memory cannot be performed at the same time. Accordingly, to program or erase flash memory, the program must first be copied from flash memory to RAM so that programming can be performed without program access from flash memory.

4. Flash Memory Register

• Flash memory control status register (FMCS)

Address	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initia
007Ан	INTE	RDYINT	WE	RDY	Reserved	Reserved	_	Reserved	000X0
	R/W	R/W	R/W	R	R/W	R/W	_	R/W	

5. Sector Configuration

The table below shows the sector configuration of flash memory and lists the addresses of each sector for both during CPU access a flash memory programming.

• Sector configuration of flash memory

Flash Memory	CPU Address	Programmer Address*		
16 Kbytes	FFFFн to C000н	1FFFFн to 1C000н		
8 Kbytes	BFFFн to A000н	1BFFFн to 1A000н		
8 Kbytes	9FFFн to 8000н	19FFFн to 18000н		
16 Kbytes	7FFFн to 4000н	17FFFн to 14000н		

* : Programmer address

The programmer address is the address to be used instead of the CPU address when programming data from a parallel flash memory programmer. Use the programmer address on programming or erasing using a general-purpose parallel programmer.

6. ROM Programmer Adaptor and Recommended ROM Programmers

Part number	Package	Adaptor Part No.	Recommended Programme Manufacturer and Model		
	-	Sunhayato Corp.	Flash Support Group, Inc.		
MB89F538-101PF MB89F538-201PF	FPT-64P-M06	Flash-64QF-32DP-8LF			
MB89F538-101PFM MB89F538-201PFM	FPT-64P-M09	Flash-64QF2-32DP-8LF2	AF9708* AF9709*		
MB89F538-101P-SH MB89F538-201P-SH	DIP-64P-M01	Flash-64SD-32DP-8LF			

* : For the version of the programmer, contact the Flash Support Group, Inc.

Enquiries	
Sunhayato Corp.: TEL	: +81-3-3984-7791
FAX	: +81-3-3971-0535
Advanced Interconnectics	: http://www.advantest.co.jp/en-index.shtml
Flash Support Group, Inc. : FAX : +81-53-4	428-8377
E-mail : support	@j-fsg.co.jp

ONE-TIME WRITING SPECIFICATIONS WITH PROM AND EPROM MICROCONTROLLERS

The MB89P538 has a PROM mode with functions equivalent to the MBM27C1001, allowing writing with a general purpose ROM writer using a proprietary adapter. Note, however, that the use of electronic signature mode is not supported.

• ROM writer adapters

With some ROM writers, stability of writing performance is enhanced by placing an 0.1 μ F capacitor between the Vcc and Vss pins. The following table lists adapters for use with ROM writers.

ROM Writer Adapters

Part number	Package	Compatible adapter
MB89P538-101PF MB89P538-201PF	FPT-64P-M06	ROM-64QF-32DP-8LA2*1
MB89P538-101PFM MB89P538-201PFM	FPT-64P-M09	ROM-64QF2-32DP-8LA
MB89P538-101P-SH MB89P538-201P-SH	DIP-64P-M01	ROM-64SD-32DP-8LA2*1
MB89P538-101PV MB89P538-201PV	LCC-64P-M16*2	ROM-64BCC-32DP-8LA-FJ

Inquiries should be addressed to Sunhayato Corp. :

TEL :+81-3-3984-7791

: +81-3-3971-0535

Advanced Interconnectics : http://www.advantest.co.jp/en-index.shtml

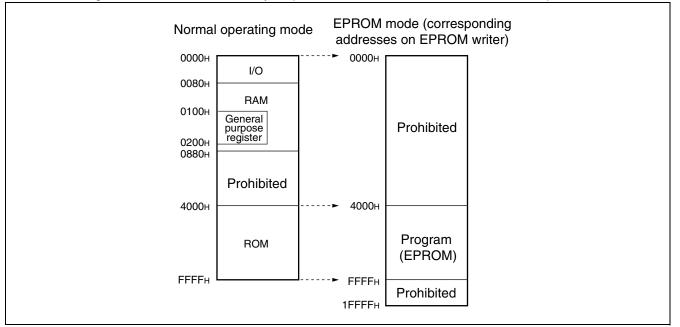
*1 : Version 3 or later should be used.

*2 : Only for ES

FAX

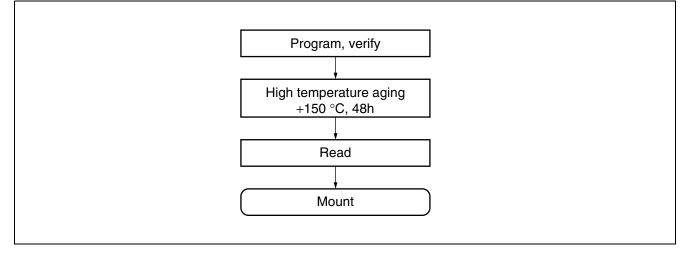
Memory map for EPROM mode

The following illustration shows a memory map for EPROM mode. There are no PROM options.



• Recommended screening conditions

Before one-time writing of microcontroller programs to PROM, high temperature aging is recommended as a screening process for chips before they are mounted.



• About writing yields

The nature of chips before one-time writing of microcontroller programs to PROM prevents the use of all-bit writing tests. Therefore it is not possible to guarantee writing yields of 100% in some cases.

■ EPROM WRITING TO PIGGY-BACK/EVALUATION CHIPS

This section describes methods of writing to EPROM on piggy-back/evaluation chips.

• EPROM model

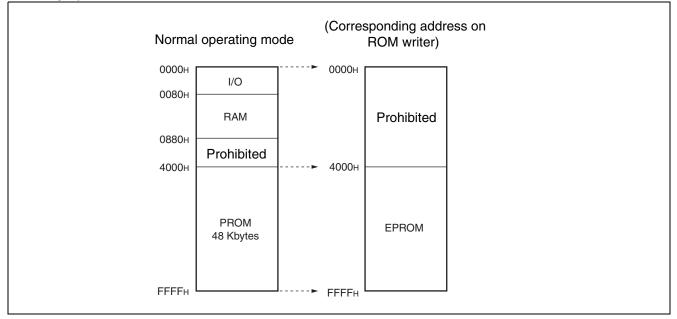
MBM27C512-20TV

• Writer adapter

For writing to EPROM using a ROM writer, use one of the writer adapters shown below (manufactured by Sunhayato Corp.).

Package	Adapter socket model			
LCC-32 (rectangular)	ROM-32LC-28DP-YG			
Inquiries should be addressed to Sunhayato Corp. : TEL : +81-3-3984-7791 FAX : +81-3-3971-0535 Advanced Interconnectics : http://www.advantes				

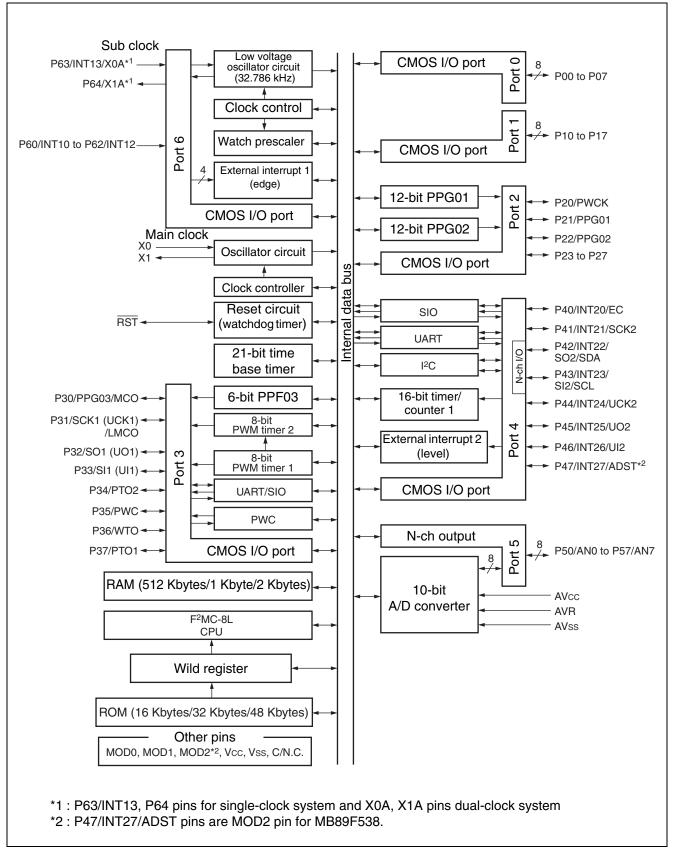
• Memory Space



• Writing to EPROM

- 1) Set up the EPROM writer for the MBM27C512.
- 2) Load program data to the ERPOM writer, in the area 4000H to FFFFH.
- 3) Use the EPROM writer to write to the area 4000H to FFFFH.

BLOCK DIAGRAM

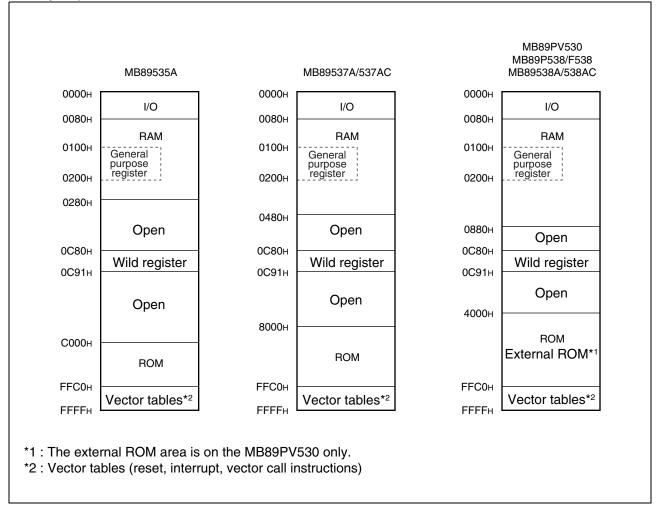


CPU CORE

1. Memory Space

The MB89530A series has 64 Kbytes of memory space, containing all I/O, data areas, and program areas. The I/O area is located at the lowest addresses, with the data area placed immediately above. The data area can be partitioned into register areas, stack areas, or direct access areas depending on the application. The program area is located at the opposite end of memory, closest to the highest addresses, and the highest part of this area is assigned to the tables of interrupt and reset vectors and vector call instructions. The following diagram shows the structure of memory space in the MB89530A series.

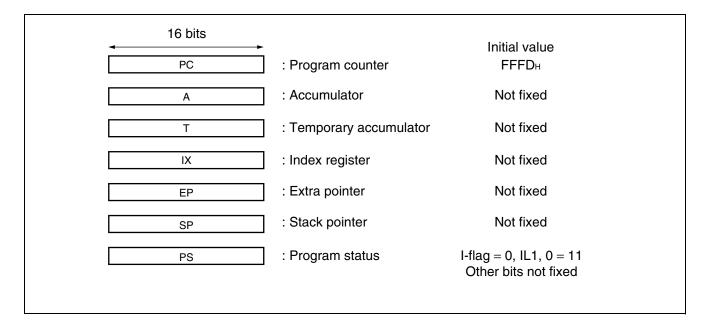
• Memory Map



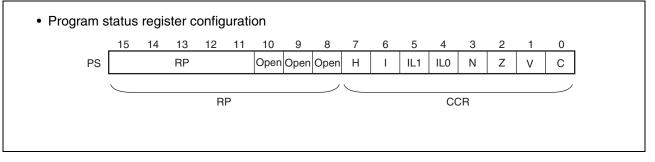
2. Registers

The F²MC-8L series has two types of registers, dedicated-use registers within the CPU, and general-purpose registers in memory.

Program counter (PC)	:	16-bit length, shows the location where instructions are stored.
Accumulator (A)	:	16-bit length, a temporary memory register for calculation operations. The lower byte is used for 8-bit data processing instructions.
Temporary accumulator (T)	:	16-bit length, performs calculations with the accumulator. The lower byte is used for 8-bit data processing instructions.
Index register (IX)	:	16-bit length, a register for index modification.
Extra pointer (EP)	:	16-bit length, a pointer indicating memory addresses.
Stack pointer (SP)	:	16-bit length, indicates stack areas.
Program status (PS)	:	16-bit length, contains register pointer and condition code.
Extra pointer (EP) Stack pointer (SP)	:	16-bit length, a pointer indicating memory addresses. 16-bit length, indicates stack areas.



In addition, the PS register can be divided so that the upper 8 bits are used as a register bank pointer (RP), and the lower 8 bits as a condition code register (CCR). (Refer to the following illustration.)



The RP register shows the address of the register bank currently being used, so that the RP value and the actual address are related by the conversion rule shown in the following illustration.

									RP upper		C	•	ation ower	code		
	"0"	"0"	"0"	"0"	"0"	"0"	"0"	"1"	R4	R3	R2	R1	R0	b2	b1	b0
Address	+	¥	¥	¥	¥	¥	¥	•	+	¥	¥	¥	+	¥	¥	+
generated	A15	A14	A13	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0

The CCR register has bits that show the content of results of calculations and transferred data, and bits that control CPU operation during interrupts.

- H-flag : Set to "1" if calculations result in carry or borrow operations from bit 3 to bit 4, otherwise set to "0". This flag is used for decimal correction instructions.
- I-flag : This flag is set to "1" if interrupts are enabled, and "0" if interrupts are prohibited. The default value at reset is "0".
- IL1, 0 : Indicates the level of the currently permitted interrupts. Only interrupt requests having a more powerful level than the value of these bits will be processed.

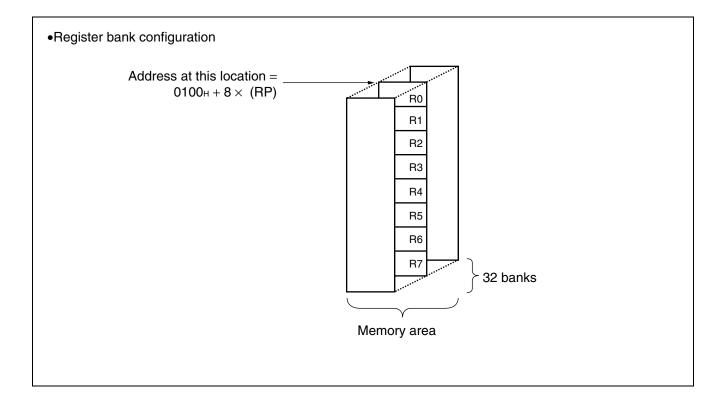
IL1	ILO	Interrupt level	Strength
0	0	1	Strong
0	1	I	≜
1	0	2	•
1	1	3	Weak

- N-flag : Set to "1" if the highest bit is "1" after a calculation, otherwise cleared to "0".
- Z-flag : Set to "1" if a calculation result is "0", otherwise cleared to "0".
- V-flag : Set to "1" if a two's complement overflow results during a calculation, otherwise cleared to "0".
- C-flag : Set to "1" if a calculation results in a carry or borrow operation from bit 7, otherwise cleared to "0". This is also the shift-out value in a shift instruction.

In addition, the following general purpose registers are available.

General purpose registers: 8 bits length, used to contain data.

The general purpose registers are 8-bit registers located in memory. There are eight such registers per bank, and the MB89530A series have up to 32 banks for use. The bank currently in use is indicated by the register bank pointer (RP).



■ I/O MAP

Address	Register name	Register description	Write/Read	Initial value
00н	PDR0	Port 0 data register	R/W	XXXXXXXXB
01 н	DDR0	Port 0 direction register	W	0000000B
02н	PDR1	Port 1 data register	R/W	XXXXXXXXB
03н	DDR1	Port 1 direction register	W	0000000B
04н to 06н		(Reserved area)		
07н	SYCC	System clock control register	R/W	Х-1 ММ1 0 Ов
08 H	STBC	Standby control register	R/W	00010в
09н	WDTC	Watchdog control register	R/W	0ХХХХв
0Ан	TBTC	Time base timer control register	R/W	00000в
0Вн	WPCR	Watch prescaler control register	R/W	000000в
0Сн	PDR2	Port 2 data register	R/W	XXXXXXXXB
0Dн	DDR2	Port 2 direction register	R/W	0000000B
0Eн	PDR3	Port 3 data register	R/W	XXXXXXXXB
0F н	DDR3	Port 3 direction register	R/W	0000000B
10 н	PDR4	Port 4 data register	R/W	XXXX 1 1 XX _B
11 н	DDR4	Port 4 direction register	R/W	000000в
12 н	PDR5	Port 5 data register	R/W	11111111
13н	PDR6	Port 6 data register	R	XXXXXXXXB
14н to 21н		(Reserved area)		
22н	SMC11	Serial mode control register 1 (UART)	R/W	0000000B
23н	SRC1	Serial rate control register (UART)	R/W	011000в
24н	SSD1	Serial status and data register (UART)	R/W	00100-1Хв
25н	SIDR1/ SODR1	Serial input/output data register (UART)	R/W	XXXXXXXXB
26н	SMC12	Serial mode control register 2 (UART)	R/W	100001в
27н	CNTR1	PWM control register 1	R/W	0000000B
28н	CNTR2	PWM control register 2	R/W	000-0000в
29н	CNTR3	PWM control register 3	R/W	-000в
2Ан	COMR1	PWM compare register 1	W	XXXXXXXXB
2Вн	COMR2	PWM compare register 2	W	XXXXXXXXB
2Сн	PCR1	PWC pulse width control register 1	R/W	000000в
2Dн	PCR2	PWC pulse width control register 2	R/W	0000000B
2Е н	RLBR	PWC reload buffer register	R/W	XXXXXXXXB
2 F н	SMC21	Serial mode control register 1 (UART/SIO)	R/W	0000000B
30н	SMC22	Serial mode control register 2 (UART/SIO)	R/W	0000000B
31н	SSD2	Serial status and data register (UART/SIO)	R/W	00001в
32н	SIDR2/ SODR2	Serial data register (UART/SIO)	R/W	XXXXXXXXB
33н	SRC2	Baud rate generator reload register	R/W	XXXXXXXXB

Address	Register name	Register description	Write/Read	Initial value
34н	ADC1	A/D control register 1	R/W	00000-0в
35н	ADC2	A/D control register 2	R/W	-000001в
36н	ADDL	A/D data register low	R/W	XXXXXXXX
37н	ADDH	A/D data register high	R/W	00в
38н	PPGC2	PPG2 control register (12-bit PPG)	R/W	0000000B
39н	PRL22	PPG2 reload register 2 (12-bit PPG)	R/W	0Х00000в
ЗАн	PRL21	PPG2 reload register 1 (12-bit PPG)	R/W	XX00000 _B
3Вн	PRL23	PPG2 reload register 3 (12-bit PPG)	R/W	XX00000 _B
3Сн	TMCR	16-bit timer control register	R/W	000000B
3Dн	TCHR	16-bit timer counter register high	R/W	0000000B
3Ен	TCLR	16-bit timer counter register low	R/W	0000000B
ЗFн	EIC1	External interrupt 1 control register 1	R/W	0000000B
40 н	EIC2	External interrupt 1 control register 2	R/W	0000000B
41н to 48н		(Reserved area)	1	
49 ⊦	DDCR	DDC select register	R/W	0в
4Aн to 4Bн		(Reserved area)	1	
4Сн	PPGC1	PPG1 control register (12-bit PPG)	R/W	0000000B
4Dн	PRL12	PPG1 reload register 2 (12-bit PPG)	R/W	0Х00000в
4Eн	PRL11	PPG1 reload register 1 (12-bit PPG)	R/W	XX000000B
4 Fн	PRL13	PPG1 reload register 3 (12-bit PPG)	R/W	XX000000B
50н	IACR	I ² C address control register	R/W	000в
51 н	IBSR	I ² C bus status register	R	0000000B
52н	IBCR	I ² C bus control register	R/W	0000000B
53н	ICCR	I ² C clock control register	R/W	000XXXXX _B
54н	IADR	I ² C address register	R/W	- XXXXXXXB
55н	IDAR	I ² C data register	R/W	XXXXXXXXB
56н	EIE2	External interrupt 2 control register	R/W	0000000B
57н	EIF2	External interrupt 2 flag register	R/W	0в
58 н	RCR1	6-bit PPG control register 1	R/W	0000000B
59 н	RCR2	6-bit PPG control register 2	R/W	0X000000B
5А н	CKR	Clock output control register	R/W	00в
5Bн to 6Fн		(Reserved area)	·	
70н	SMR	Serial mode register (SIO)	R/W	0000000B
71 н	SDR	Serial data register (SIO)	R/W	XXXXXXXXB
72н	PURR0	Port 0 pull-up resistance register	R/W	11111111
73н	PURR1	Port 1 pull-up resistance register	R/W	11111111в
74 _H	PURR2	Port 2 pull-up resistance register	R/W	11111111
75н	PURR3	Port 3 pull-up resistance register	R/W	11111111в
76н	PURR4	Port 4 pull-up resistance register	R/W	111111в
77н	WREN	Wild register enable register	R/W	000000B
			•	(Continued)

Address	Register name	Register description	Write/Read	Initial value		
78 н	WROR	Wild register data test register	R/W	000000B		
79 н	PURR6	Port 6 pull-up resistance register	R/W	11111в		
7Ан	FMCS	Flash memory control status resister	R/W	0 0 0X0 0 - 0		
7Вн	ILR1	Interrupt level setting register 1	W	11111111		
7Сн	ILR2	Interrupt level setting register 2	W	11111111		
7Dн	ILR3	Interrupt level setting register 3	W	11111111		
7 Ен	ILR4	Interrupt level setting register 4	W	11111111		
7 F н	ITR	Interrupt test register	Access prohibited	XXXXXX0 0		
С80н	WRARH1	Upper address setting register 1	R/W	XXXXXXXX		
С81н	WRARL1	Lower address setting register 1	R/W	XXXXXXXX		
С82н	WRDR1	Data setting register 1	R/W	XXXXXXXX		
С83н	WRARH2	Upper address setting register 2	XXXXXXXX			
С84н	WRARL2	Lower address setting register 2	ower address setting register 2 R/W			
С85н	WRDR2	Data setting register 2	R/W	XXXXXXXX		
С86н	WRARH3	Upper address setting register 3	R/W	XXXXXXXX		
С87н	WRARL3	Lower address setting register 3	R/W	XXXXXXXX		
С88н	WRDR3	Data setting register 3	R/W	XXXXXXXX		
С89н	WRARH4	Upper address setting register 4	R/W	XXXXXXXX		
С8Ан	WRARL4	Lower address setting register 4	R/W	XXXXXXXX		
С8Вн	WRDR4	Data setting register 4	R/W	XXXXXXXX		
С8Сн	WRARH5	Upper address setting register 5	R/W	XXXXXXXX		
C8DH	WRARL5	Lower address setting register 5	R/W	XXXXXXXX		
С8Ен	WRDR5	Data setting register 5	R/W	XXXXXXXX		
C8FH	WRARH6	Upper address setting register 6	R/W	XXXXXXXX		
С90н	WRARL6	Lower address setting register 6	R/W	XXXXXXXX		
С91н	WRDR6	Data setting register 6	R/W	XXXXXXXX		

• Description of write/read symbols :

- R/W : read/write enabled
- R : Read only
- W : Write only

• Description of initial values :

- 0 : This bit initialized to "0".
- 1 : This bit initialized to "1".
- X : The initial value of this bit is not determined.
- M : The initial value of this bit is a mask option.
- : This bit is not used.

Note : Do not use reserved spaces.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

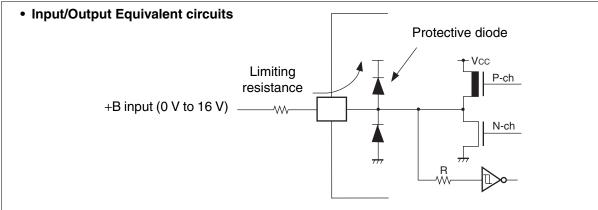
Parameter	Symbol	Rat	ing	Unit	Remarks
Parameter	Symbol	Min	Max	Unit	Remarks
Supply voltage*1	Vcc, AVcc	Vss - 0.3	Vss + 6.0	V	MB89535A/537A/538A*2 MB89537AC/538AC
	AVR	Vss - 0.3	Vss + 6.0	V	MB89F538/P538 MB89PV530
Input voltage*1	V	Vss - 0.3	Vcc + 0.3	V	Other than P42, P43
input voltage	VI	$V_{\text{SS}}-0.3$	Vss + 6.0	V	P42, P43
Output voltage*1	Vo	$V_{\text{SS}}-0.3$	Vcc + 0.3	V	Other than P42, P43
Output Voltage	VO	$V_{\text{SS}}-0.3$	Vss + 6.0	V	P42, P43
Maximum clamp current		- 2.0	+ 2.0	mA	*3
Total maximum clamp current	Σ clamp		20	mA	*3
"L" level maximum output current	lo∟	_	15	mA	
"L" level average output current	Iolav	_	4	mA	Average value (operating current × operating duty)
"L" level maximum total output current	ΣΙοι		100	mA	
"L" level average total output current	ΣΙοιαν		40	mA	Average value (operating current × operating duty)
"H" level maximum output current	Іон	_	-15	mA	
"H" level average output current	Іонач	_	-4	mA	Average value (operating current × operating duty)
"H" level maximum total output current	ΣІон		-50	mA	
"H" level average total output current	ΣΙοήαν		-20	mA	Average value (operating current × operating duty)
Current consumption	PD		300	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

*1 : The parameter is based on AVss = Vss = 0 V.

 *2 : AVcc and Vcc are to be used at the same potential. AVR should not exceed AVcc + 0.3 V.

(Continued)

- *3 : Applicable to pins : P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40, P41, P44 to P47, P60 to P64 • Use within recommended operating conditions.
 - Use at DC voltage (current) .
 - The +B signal should always be applied with a limiting resistance placed between the +B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the Vcc pin, and this may affect other devices.
 - Note that if a +B signal is input when the microcontroller current is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the power-on result.
 - Care must be taken not to leave the +B input pin open.
 - Note that analog system input/output pins other than the A/D input pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signal input.
 - Sample recommended circuits :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

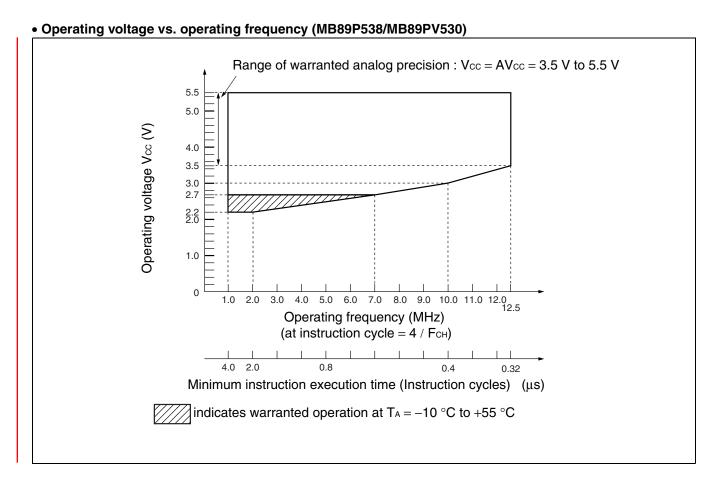
2. Recommended Operating Conditions

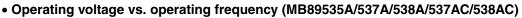
(AVss = Vss = 0 V)

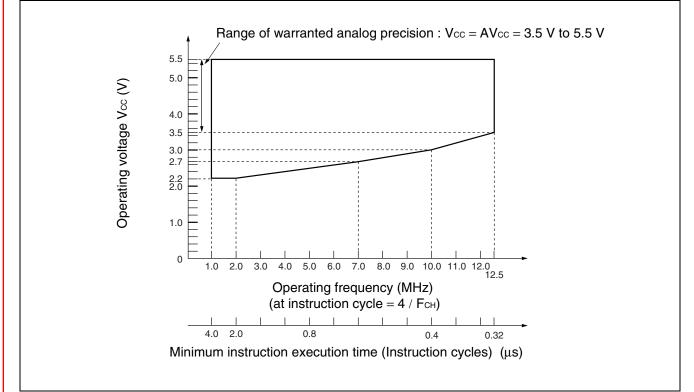
Parameter	Symbol	Va	lue	Unit	Remarks		
Farameter	Symbol	Min	Мах	Unit			
		2.2*	5.5	V	Range warranted for normal operation	MB89535A MB89537A/538A	
		1.5	5.5	V	RAM status in stop mode	MB89537AC/ 538AC	
	Vcc, AVcc	2.7*	5.5	V	Range warranted for normal operation	MB89P538	
Supply voltage		1.5	5.5	V	RAM status in stop mode	MB89PV530	
		3.5	5.5	V	Range warranted for normal operation	– MB89F538	
		3.0	5.5	V	RAM status in stop mode		
	AVR	3.5	AVcc	V			
Operating temperature	TA	-40	+85	°C			

* : Varies according to frequency used, and instruction cycle.

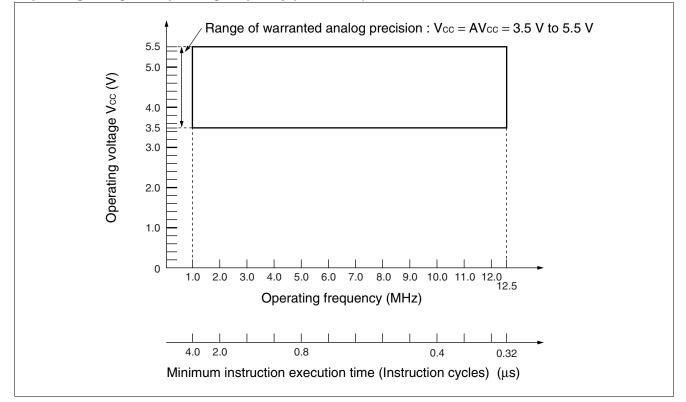
Refer to "Operating voltage vs. operating frequency (MB89P538/MB89PV530)", "Operating voltage vs. operating frequency (MB89535A/537A/538A/537AC/538AC)", "Operating voltage vs. operating frequency (MB89F538)" and "5. A/D Converter Electrical Characteristics".







• Operating voltage vs. operating frequency (MB89F538)



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

3. DC Characteristics

(1) Supply Voltage at 5.0 (V)

_					Value			-40 0 10 +65 0)
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
	Vін	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P64, SI1, SI2		0.7 Vcc	_	Vcc + 0.3	V	
"H" level input voltage	Vins	RST, MOD0, MOD1, INT20 to INT27, UCK1, UI1, INT10 to INT13, SCK1, EC, PWCK, PWC, SCK2, UCK2, UI2, ADST	_	0.8 Vcc		Vcc + 0.3	V	
	VIHSMB	SCL, SDA		Vss + 1.4		Vss + 5.5	V	With SMB input buffer selected*
	VIHI2C	SCL, SDA		0.7 Vcc		Vss + 5.5	V	With I ² C input buffer selected*
	VIL P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P64, SI1, SI2			Vss - 0.3	_	0.3 Vcc	V	
"L" level input voltage	Vils	RST, MOD0, MOD1, INT20 to INT27, UCK1, UI1, INT10 to INT13, SCK1, EC, PWCK, PWC, SCK2, UCK2, UI2, ADST		Vss - 0.3		0.2 Vcc	V	
	VILSMB	SCL, SDA		Vss - 0.3		Vss + 0.6	V	With SMB input buffer selected*
	VILI2C	SCL, SDA		Vss - 0.3		0.3 Vcc	V	With I ² C input buffer selected*
Open drain	V _{D1}	P50 to P57				Vcc + 0.3	V	
output applied voltage	V _{D2}	P42, P43		Vss – 0.3		Vss + 5.5	V	
"H" level output voltage			Іон = –2.0 mA	4.0			V	
salpar voltage		P25 to P27	Іон = –3.0 mA					
"L" level output voltage	Vol	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, RST	lo∟ = 4.0 mA			0.4	V	

(AVcc = Vcc = 5.0 V, AVss = Vss = 0 V, T_A = -40 °C to +85 °C)

		D .	.		Value			
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
Input leak current (Hi-Z output leak current)	lu	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P60 to P64	0.0 V < VI < Vcc	-5		+5	μA	With no pull-up re- sistance specified
Open drain output leak current	Iliod	P42, P43	0.0 V < V ₁ < V _{SS} + 5.5 V			5	μΑ	
Pull-up resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40, P41, P44 to P47, P60 to P64, RST	$V_{1} = 0.0 V$	25	40	100	kΩ	With pull-up resistance speci- fied. The RST sig- nal is excluded.
			E 10.0141		15	20	mA	MB89P538/ PV530
	Icc1		Fсн = 10.0 MHz Vcc = 5.0 V		6	10	mA	MB89F538
		$t_{inst} = 0.4 \ \mu s$		8	13	mA	MB89535A/7A/8A MB89537AC/ 538AC	
		Vcc	_		5	8.5	mA	MB89P538/ PV530
	Icc2		Fсн = 10.0 MHz Vcc = 5.0 V		1.5	3	mA	MB89F538
			$t_{\text{inst}}=6.4~\mu s$		1.5	3	mA	MB89535A/7A/8A MB89537AC/ 538AC
Supply					5	7	mA	Sleep mode MB89P538/ PV530
current	Iccs1		F _{CH} = 10.0 MHz V _{CC} = 5.0 V		3	5	mA	Sleep mode MB89F538
			$t_{inst} = 0.4 \ \mu s$		2.5	5	mA	Sleep mode MB89535A/7A/8A MB89537AC/ 538AC
					1.5	3	mA	Sleep mode MB89P538/ PV530
	Iccs2		Fсн = 10.0 MHz Vcc = 5.0 V		1	2	mA	Sleep mode MB89F538
			$t_{inst} = 6.4 \ \mu s$		1	2	mA	Sleep mode MB89535A/7A/8A MB89537AC/ 538AC

(AVcc = Vcc = 5.0 V, AVss = Vss = 0 V, T_A = -40 °C to +85 °C)

(Continued)

				- ,-	Value			= -40 °C to +85 °C
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
			_		3	7	mA	Sub mode MB89P538/ PV530
	lcc∟		Fc∟ = 32.768 kHz Vcc = 5.0 V		400	800	μA	Sub mode MB89F538
			$T_A = +25 \ ^\circ C$	_	50	85	μA	Sub mode MB89535A/7A/8A MB89537AC/ 538AC
		Vcc	_		30	50	μA	Sub, sleep mode MB89P538/ PV530
Supply current	Iccls		Fc∟ = 32.768 kHz Vcc = 5.0 V		15	30	μA	Sub, sleep mode MB89F538
			T _A = +25 °C	_	15	30	μA	Sub, sleep mode MB89535A/7A/8A MB89537AC/ 538AC
	Ісст		$F_{CL} =$ 32.768 kHz $V_{CC} = 5.0 V$ $T_{A} = +25 \ ^{\circ}C$	_	5	15	μA	Watch mode, main stop
	Іссн		$T_A = +25 \ ^\circ C$		3	10	μA	Sub, stop modes
-	la	AVcc	Fсн = 10.0 MHz		4	6	mA	A/D conversion running
	Іан		$T_A = +25 \ ^\circ C$		1	5	μA	A/D stopped
Input capacitance	CIN	Except Vcc, Vss, AVcc, AVss	f = 1 MHz		5	15	pF	

*: The MB89PV530/P538/537AC/538AC have a built-in I²C function, and a choice of input buffers by software setting. MB89535A/537A/538A have no built-in I²C functions, and therefore this standard does not apply.

(2) Supply Vo	oltage at	3.0 (V) (except MB89F	,	c = 3.0 V, A	Vss = Vs	s = 0 V, Ta	= -40	°C to +85 °C)
Parameter	Symbol	Pin name	Condition	,	Value	Unit	Remarks	
rarameter	Symbol	rinname	Condition	Min	Тур	Max	Onit	Tiernarks
	∨н	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P64, SI1, SI2		0.7 Vcc	_	Vcc + 0.3	V	
"H" level input voltage	ViHs	RST, MOD0, MOD1, INT20 to INT27, UCK1, UI1, INT10 to INT13, SCK1, EC, PWCK, PWC, SCK2, UCK2, UI2, ADST		0.8 Vcc		Vcc + 0.3	V	
	VIHSMB		_	Vss + 1.4		V _{SS} + 5.5	v	With SMB input buffer selected*
	VIHI2C	SCL, SDA		0.7 Vcc	_	V _{SS} + 5.5	V	With I ² C input buffer selected*
	Vı∟	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P64, SI1, SI2		Vss - 0.3		0.3 Vcc	v	
"L" level input voltage	Vils	RST, MOD0, MOD1, INT20 to INT27, UCK1, UI1, INT10 to INT13, SCK1, EC, PWCK, PWC, SCK2, UCK2, UI2, ADST		Vss - 0.3		0.2 Vcc	v	
	VILSMB		_	Vss - 0.3		Vss + 0.6	V	With SMB input buffer selected*
	VILI2C	SCL, SDA		Vss - 0.3		0.3 Vcc	V	With I ² C input buffer selected*
Open drain	V _{D1}	P50 to P57				Vcc + 0.3	V	
output applied voltage	V _{D2}	P42, P43		Vss – 0.3	_	V _{SS} + 5.5	v	
"H" level output voltage	Vон	P00 to P07, P10 to P17, P20 to P24, P30 to P37, P40, P41, P44 to P47	Іон = -2.0 mA	2.4		_	v	
· · · · ·		P25 to P27	Iон = -3.0 mA					
"L" level output voltage	Vol	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, RST	lo∟ = 4.0 mA	_	_	0.4	V	

(Continued)

(AVcc = Vcc = 3.0 V, AVss = Vss = 0 V, $T_A = -40 \text{ °C to } +85 \text{ °C}$)

_ .		- :			Value			
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
Input leak current (Hi-Z output leak current)	lu	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P60 to P64	$0.0 V < V_1 <$	-5		+5	μA	With no pull-up resistance specified
Open drain output leak current		P42, P43	$0.0 V < V_1 < V_{SS} + 5.5 V$			5	μA	
Pull-up resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40, P41, P44 to P47, P60 to P64, RST	$V_{1} = 0.0 V$	25	70	100	kΩ	With pull-up resistance specified. The RST signal is excluded.
	Icc1		$\label{eq:Fch} \begin{split} F_{\text{CH}} &= 10.0 \; MHz \\ t_{\text{inst}} &= 0.4 \; \mu s \end{split}$		6	10	mA	
	Icc2		$\label{eq:Fch} \begin{split} F_{\text{CH}} &= 10.0 \; MHz \\ t_{\text{inst}} &= 6.4 \; \mu s \end{split}$		1.5	3	mA	
Iccs1	Iccs1		$\label{eq:Fch} \begin{split} F_{\text{CH}} &= 10.0 \; MHz \\ t_{\text{inst}} &= 0.4 \; \mu s \end{split}$		2	4	mA	Sleep mode
	Iccs2		$\label{eq:Fch} \begin{split} F_{\text{CH}} &= 10.0 \; MHz \\ t_{\text{inst}} &= 6.4 \; \mu s \end{split}$		1	2	mA	Sleep mode
			FcL =		1	3	mA	Sub modes MB89P538/PV530
Supply current	lcc∟	Vcc	32.768 kHz Vcc = 3.0 V T _A = +25 °C		20	50	μΑ	Sub modes MB89535A/7A/8A MB89537AC/538AC
	Iccls		$ F_{CL} = \\ 32.768 \ \text{kHz} \\ V_{CC} = 3.0 \ \text{V} \\ T_{A} = +25 \ ^{\circ}\text{C} $		15	30	μA	Sub, sleep modes
	Ісст		$F_{CL} = \\ 32.768 \text{ kHz} \\ V_{CC} = 3.0 \text{ V} \\ T_{A} = +25 \text{ °C} \\ \end{cases}$		5	15	μA	Watch mode, main stop
	Іссн		T _A = +25 °C		1	5	μA	Sub, stop modes
	la	AVcc	F _{CH} = 10.0 MHz		1	3	mA	A/D conversion running
	Іан		$T_A = +25 \ ^\circ C$		1	5	μA	A/D stopped
Input capacitance	Cin	Except Vcc, Vss, AVcc, AVss	f = 1 MHz		5	15	pF	

*: The MB89PV530/P538/537AC/538AC have a built-in I²C function, and a choice of input buffers by software setting. MB89535A/537A/538A have no built-in I²C functions, and therefore this standard does not apply.

4. AC Characteristics

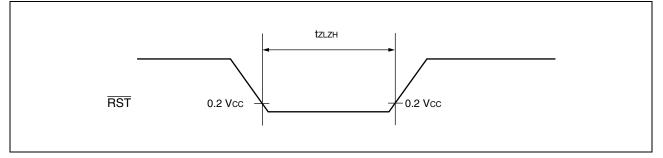
(1) Reset Timing

 $(V_{CC} = 5.0 \text{ V}, \text{ AVss} = \text{Vss} = 0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

Parameter	Symbol	Condition	Val	Unit	
Farameter	Symbol	Condition	Min	Max	Onic
RST "L" pulse width	tzlzн		48 theyl		ns

Notes: • there is the main clock oscillator period.

• If the reset pulse applied to the external reset pin (RST) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin (RST).

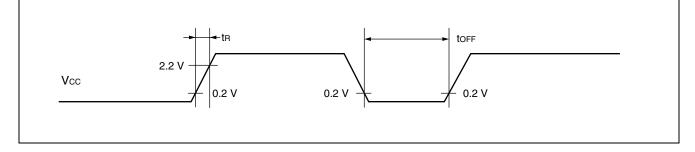


(2) Power-on Reset

(AVss = Vss = 0 V, $T_A = -40 \ ^{\circ}C$ to +85 $^{\circ}C$)

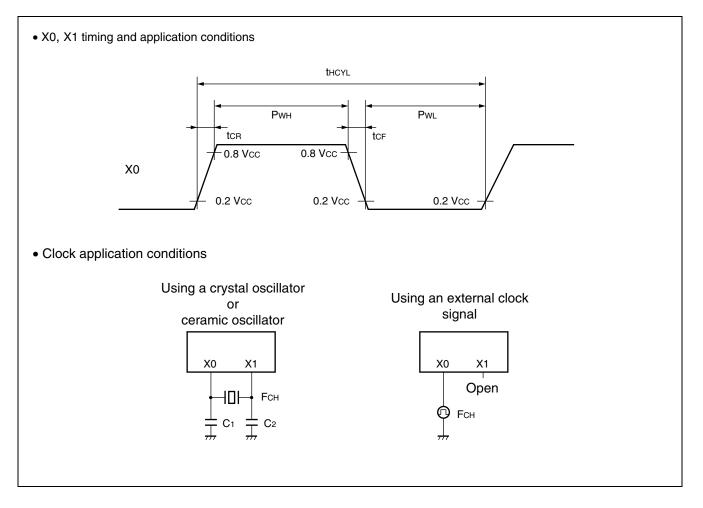
Parameter	Symbol Condition		Va	lue	Unit	Remarks	
Falameter	Symbol	Condition	Min	Max	Unit	Heinarks	
Power on time	tR		0.5	50	ms		
Power shutoff time	toff	_	1	_	ms	Waiting time until power-on	

Note : Be sure that the power supply will come on within the selected oscillator stabilization period. Also, when varying the supply voltage during operation, it is recommended that the supply voltage be increased gradually.

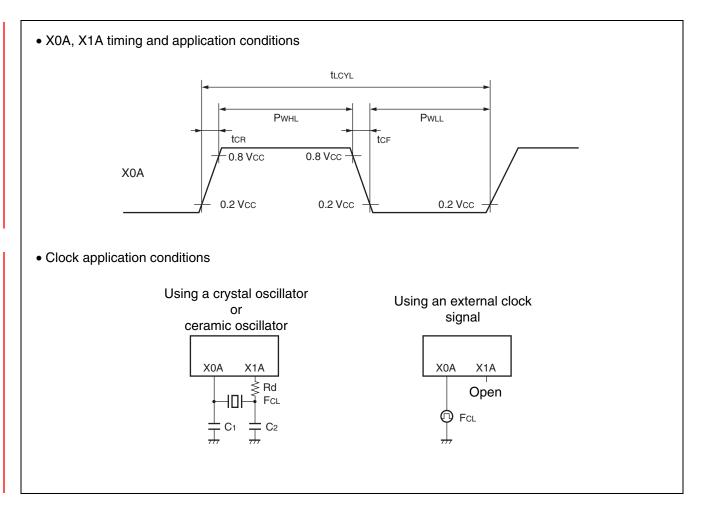


(3) Clock Timing Standards

					(7133 -	- 103 - 0	v , 1A –	-40 C (0 $+65$ C)
Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
Falameter	Symbol		Condition	Min	Тур	Max	Unit	Homano
Clock frequency	Fсн	X0, X1		1	—	12.5	MHz	Main clock
Clock frequency	Fc∟	X0A, X1A			32.768	_	kHz	Sub clock
Clock cycle time	t HCYL	X0, X1		80		1000	ns	Main clock
	t LCYL	X0A, X1A			30.5	_	μs	Sub clock
Input clock pulso width	Рwн Pw∟	X0	—	20			ns	External clock
Input clock pulse width	Pwhl Pwll	X0A			15.2		μs	External clock
Input clock rise, fall time	tcĸ tc⊧	X0				10	ns	External clock



$(AVss = Vss = 0 V, T_A = -40 \circ C to +85 \circ C)$



(4) Instruction Cycle

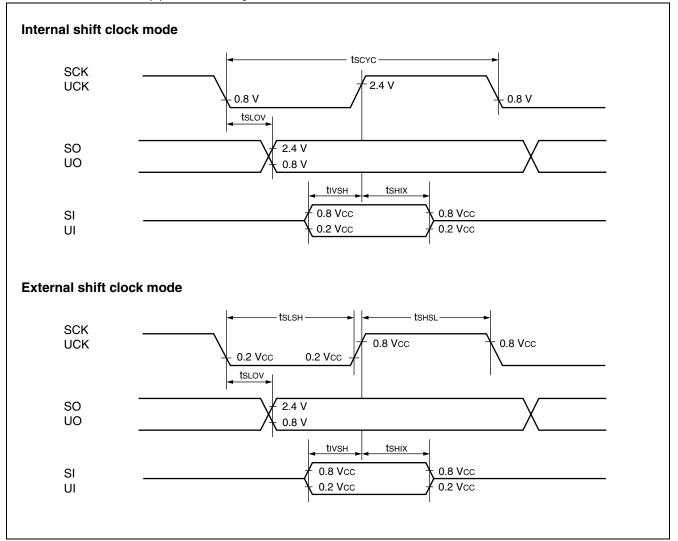
(AVss = Vss = 0 V, $T_A = -40 \ ^{\circ}C$ to +85 $^{\circ}C$)

Parameter	Symbol	Rated value	Unit	Remarks
Instruction cycle (minimum instruction	tinst	4/Fсн, 8/Fсн, 16/Fсн, 64/Fсн	μs	Operating at $F_{CH} = 12.5 \text{ MHz}$ (4/F _{CH}) $t_{inst} = 0.32 \mu\text{s}$
execution time)		2/FcL	μs	Operating at FcL = 32.768 kHz tinst = 61.036 μ s

(5) Serial I/O Timing

Parameter	Symbol	Pin name	Condition	Va	Unit	
Faldilletei	Symbol	Finitianie	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK, UCK		2 tinst		μs
SCK↓→SO	tslov	SCK, SO, UCK, UO	Internal clock	-200	+200	ns
Valid SI→SCK↑	tıvsн	SI, SCK, UI, UCK	operation	200		ns
SCK↑→valid SI hold time	tsнix	SCK, SI, UCK, UI		200		ns
Serial clock "H" pulse width	tsнs∟	SCK, UCK		1 t _{inst}		μs
Serial clock "L" pulse width	ts∟sн	30K, 00K	External	1 t _{inst}		μs
SCK↓→SO time	tslov	SCK, SO, UCK, UO	clock	0	200	ns
Valid SI→SCK↑	tıvsн	SI, SCK, UI, UCK	operation	200		ns
$SCK^{\uparrow} \rightarrow valid SI hold time$	tsнix	SCK, SI, UCK, UI		200		ns

Note : For tinst refer to "(4) Instruction Cycle".

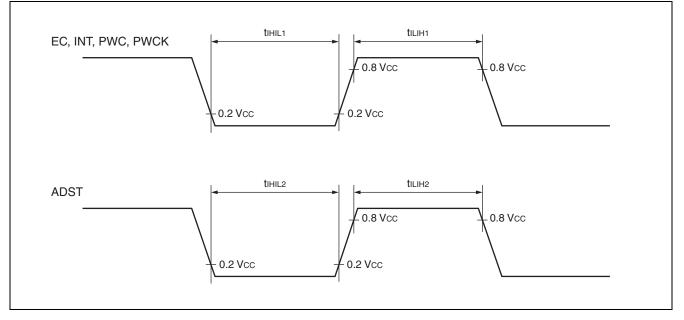


(Vcc = 5.0 V, AVss = Vss = 0 V, T_A = -40 °C to +85 °C)

(6) Peripheral Input Timing

(·)···································		(Vcc =	= 5.0 V, AVss =	= Vss = 0 V, 1	Γ _A = −40 °C to	• +85 °C)
Parameter	Symbol	Pin name	Condition	Va	Unit	
Falameter	Symbol	Fiii lidille	Condition	Min	Max	Unit
Peripheral input "H" level pulse width 1	tılıH1	INT10 to INT13, INT20 to INT27,	_	2 tinst	_	μs
Peripheral input "L" level pulse width 1	tıнı∟1	EC, PWC, PWCK		2 tinst	_	μs
Peripheral input "H" level pulse width 2	tilih2	ADST	_	2 ⁸ t _{inst}		μs
Peripheral input "L" level pulse width 2	tihil2			2 ⁸ t _{inst}	_	μs

Note : For tinst refer to " (4) Instruction Cycle".



(7) I²C Timing

			($(V_{CC} = 5.0 \text{ V}, \text{ AVss} = \text{Vss} = 0 \text{ V}, \text{ I}_{A} = -40 ^{\circ}\text{C} \text{ to } +80 ^{\circ}\text{C} ^{\circ}\text{C} \text{ to } +80 ^{\circ}\text{C} ^{\circ}\text{C} \text{ to } +80 ^{\circ}\text{C} ^{\circ} ^{\circ}\text{C} ^{\circ} ^{\circ} ^{\circ}\text{C} ^{\circ} $				
Parameter	Symbol	Pin	Condition	Va	lue	Unit	Remarks	
raiameter	Symbol	name	Condition	Min	Max	Unit	nema ks	
Start condition output	t sta	SCL SDA	_	$\begin{array}{c} 1 \ / \ 4 \ t_{inst} \times \\ m \times n - 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \ t_{inst} \times \\ m \times n + 20 \end{array}$	ns	Master only	
Stop condition output	tsто	SCL SDA		$\begin{array}{c} 1 \ / \ 4 \ t_{\text{inst}} \times \\ (m \times n + 8) \ - 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \ t_{inst} \times \\ (m \times n + 8) \ + 20 \end{array}$	ns	Master only	
Start condition detection	t sta	SCL SDA		1 / 4 t _{inst} × 6 + 40		ns		
Stop condition detection	tsто	SCL SDA		1 / 4 t _{inst} × 6 + 40		ns		
Restart condition output	t stasu	SCL SDA		$\begin{array}{c} 1 \ / \ 4 \ t_{\text{inst}} \times \\ (m \times n + 8) \ - 20 \end{array}$	$\frac{1 \ / \ 4 \ t_{inst} \times}{(m \times n + 8) \ + 20}$	ns	Master only	
Restart condition detection	t stasu	SCL SDA		1 / 4 tinst × 4 + 40		ns		
SCL output "L" width	t∟ow	SCL		$\begin{array}{c} 1 \ / \ 4 \ t_{\text{inst}} \times \\ m \times n - 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \ t_{inst} \times \\ m \times n + 20 \end{array}$	ns	Master only	
SCL output "H" width	tніgн	SCL		$\begin{array}{c} 1 \ / \ 4 \ t_{inst} \times \\ (m \times n + 8) \ - 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \ t_{inst} \times \\ (m \times n + 8) \ + 20 \end{array}$	ns	Master only	
SDA output delay time	too	SDA		$1 / 4 t_{inst} imes 4 - 20$	1 / 4 $t_{inst} \times 4 + 20$	ns		
Setup after SDA output interrupt interval	toosu	SDA		1 / 4 tinst × 4 - 20		ns		
SCL input "L" width	t∟ow	SCL		$1 / 4 t_{\text{inst}} \times 6 + 40$		ns		
SCL input "H" width	tніgн	SCL		$1 / 4 t_{inst} \times 2 + 40$		ns		
SDA input setup	tsu	SDA		40		ns		
SDA input hold	tно	SDA		0		ns		

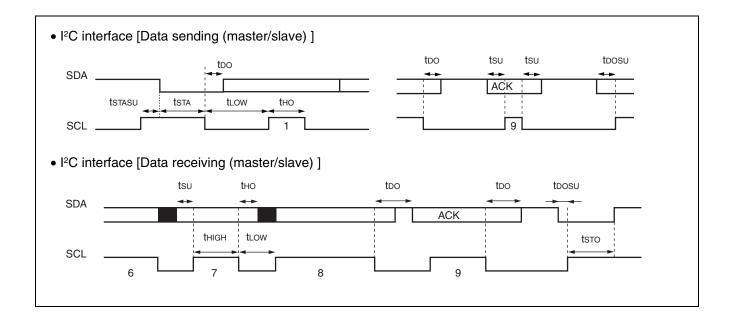
(Vcc = 5.0 V, AVss = Vss = 0 V, T_A = -40 °C to +85 °C)

Notes : • For tinst refer to " (4) Instruction Cycle".

• The value "m" in the above table is the value from the shift clock frequency setting bits (CS4, CS3) in the I²C clock control register "ICCR". For details, refer to the register description in the hardware manual.

• The value 'n' in the above table is the value from the shift clock frequency setting bits (CS2, CS0) in the I²C clock control register "ICCR". For details, refer to the register description in the hardware manual.

- \bullet t_DOSU appears when the interrupt period is longer than the SCL "L" width.
- The rated values for SDA and SCL assume a start up time of 0 ns.



5. A/D Converter Electrical Characteristics

(1) MB89535A/537A/537AC/538A/538AC/P538/PV530

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
Farameter				Min	Тур	Max	Unit	nemarks
Resolution capability						10	bit	
Total error				—		±3.0	LSB	
Linear error						±2.5	LSB	
Differential linear error					_	±1.9	LSB	
Zero transition voltage	Vот		AVR = AVcc	AVss – 1.5 LSB	AV _{ss} + 0.5 LSB	AV _{SS} + 2.5 LSB	mV	AVcc = Vcc
Full scale transition voltage	VFST			AVR – 3.5 LSB	AVR – 1.5 LSB	AVR + 1.5 LSB	mV	
Inter-channel variation						4.0	LSB	
Conversion time					60 t _{inst}		μs	*
Sampling time					16 t inst		μs	
Analog input current	lain	AN0 to				10	μA	
Analog input voltage	VAIN	AN7		0		AVR	V	
Reference voltage				$AV_{\text{SS}} + 3.5$		AVcc	V	
Reference voltage	IR	AVR	A/D running	—	400		μA	
supply current	IRH]	A/D off			5	μA	

* : Includes sampling time.

Note : For tinst refer to "4. AC Characteristics (4) Instruction Cycle".

(2) MB89F538

Demonster	Symbol Pin nan	D'	e Condition	Value				
Parameter		Pin name		Min	Тур	Max	Unit	Remarks
Resolution capability						10	bit	
Total error						±5.0	LSB	
Linear error				—		±2.5	LSB	1
Differential linear error				—		±1.9	LSB	
Zero transition voltage	Vот		AVR = AVcc	AVss – 1.5 LSB	AVss + 0.5 LSB	AV _{SS} + 4.5 LSB	mV	AVcc = Vcc
Full scale transition voltage	VFST		AVR – 6.5 LSB	AVR – 1.5 LSB	AVR + 1.5 LSB	mV		
Inter-channel variation						4.0	LSB	
Conversion time	—				60 tinst	_	μs	*
Sampling time				—	16 t _{inst}		μs	
Analog input current	Iain	AN0 to		—	_	10	μA	
Analog input voltage	VAIN	AN7		0		AVR	V	
Reference voltage				AVss + 3.5		AVcc	V	
Reference voltage	IR	AVR	A/D running		400		μA	
supply current	IRH		A/D off			5	μA	

* : Includes sampling time.

Note : For tinst refer to "4. AC Characteristics (4) Instruction Cycle".

(3) A/D Converter Terms and Definitions

Resolution

The level of analog variation that can be distinguished by the A/D converter.

• Linear error (unit : LSB)

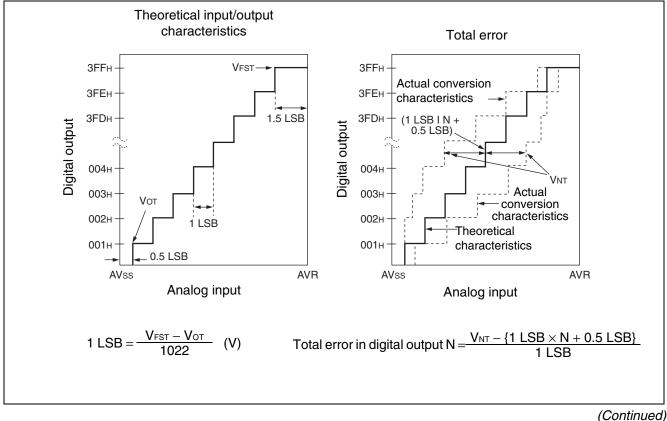
The deviation between the value along a straight line connecting the zero transition point ("00 0000 0000" $\leftarrow \rightarrow$ "00 0000 0001") of a device and the full-scale transition point ("11 1111 1110" $\leftarrow \rightarrow$ "11 1111 1111"), compared with the actual conversion values obtained.

• Differential linear error (Unit : LSB)

The deviation from the theoretical input voltage required to produce a change of 1 LSB in output code.

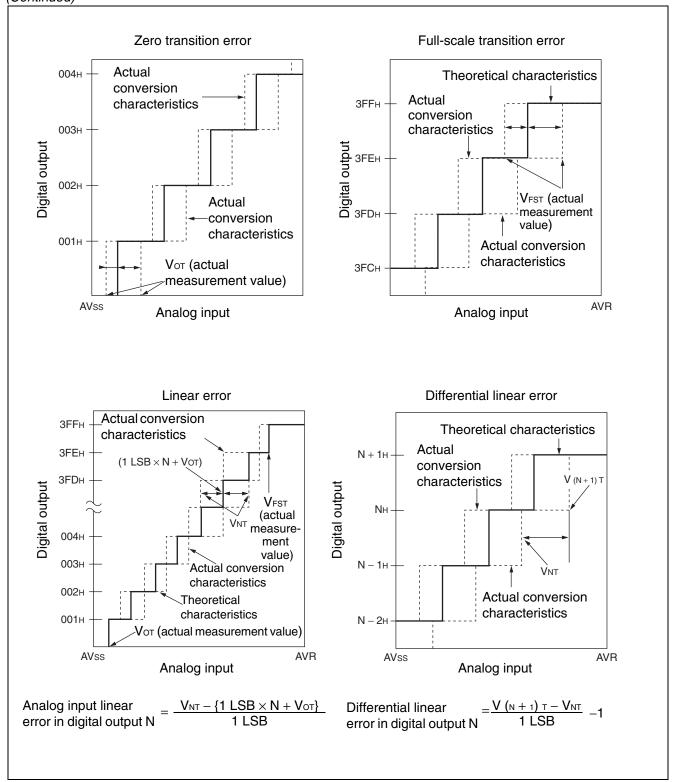
• Total error (Unit : LSB)

The difference between theoretical conversion value and actual conversion value.



50

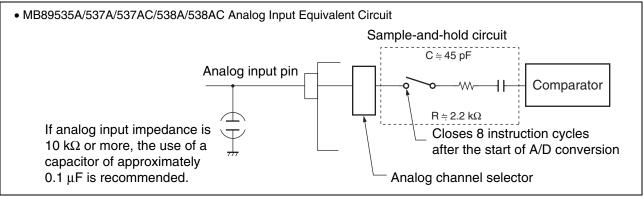


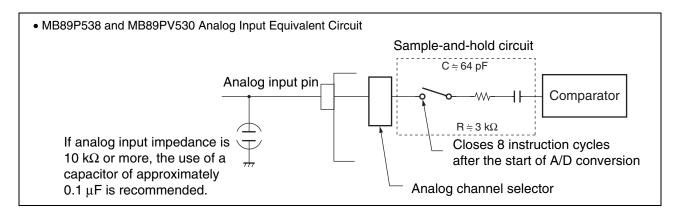


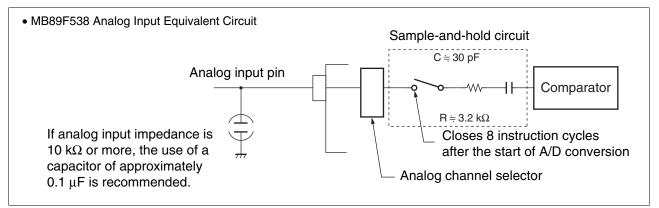
(4) Precautionary Information

Input Impedance of Analog Input Pins

The A/D converter of MB89530A has a sample & hold circuit as shown below, which uses a sample-and-hold capacitor to obtain the voltage at the analog input pin for 8 instruction cycles following the start of A/D conversion. For this reason if the external circuits providing the analog input signal have high output impedance, the analog input voltage may not stabilize within the analog input sampling time. It is therefore recommended that the output impedance of external circuits be reduced to 10 k Ω or less.







About error

The smaller the absolute value IAVR - AVssI is, the greater the relative error becomes.

6. Flash Memory

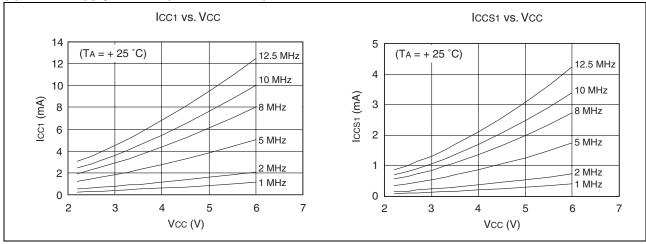
• Flash memory programming/erase characteristics

Parameter		Conditions		Value	Unit	Remarks	
			Min	Тур	Max	Unit	nemarks
Sector erase time	Per 1 sector, Constant value independent with sector capacitance	T₄ = +25 °C,		1	15	S	*
		Vcc = 5.0 V		8	3600	μs	
Chip erase time				5	—	S	*
Program/Erase cycle			10000			cycle	

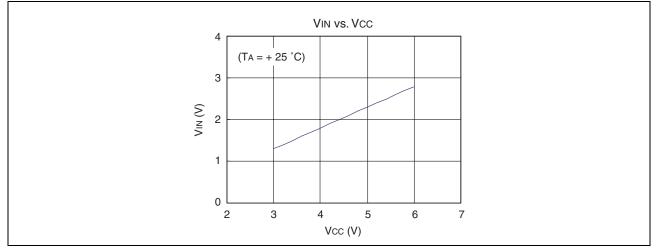
* : Excludes internal programming time before erase.

■ EXAMPLE CHARACTERISTICS (MB89538A)

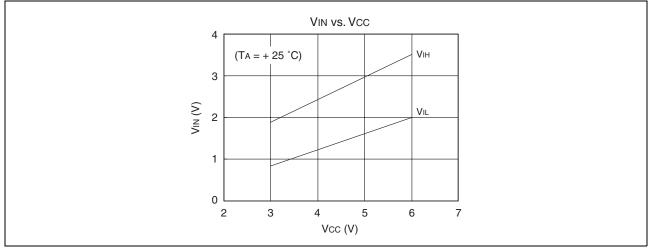
(1) Power Supply Current (External Clock)



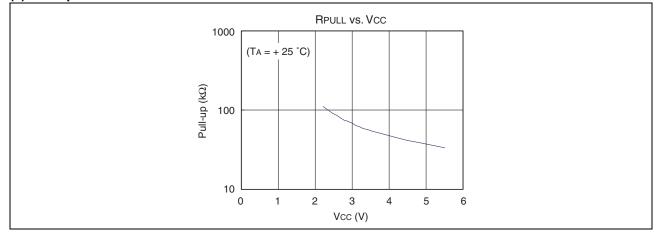
(2) "H" Level Input Voltage/ "L" Level Input Voltage (CMOS Input)



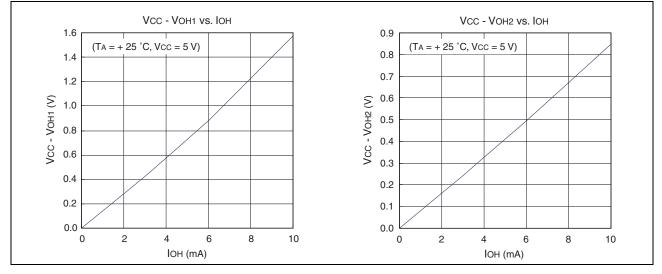
(3) "H" Level Input Voltage / "L" Level Input Voltage (Hysteresis Input)



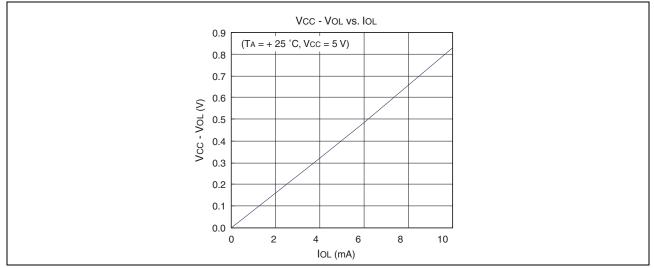
(4) Pull-up Resistor Value



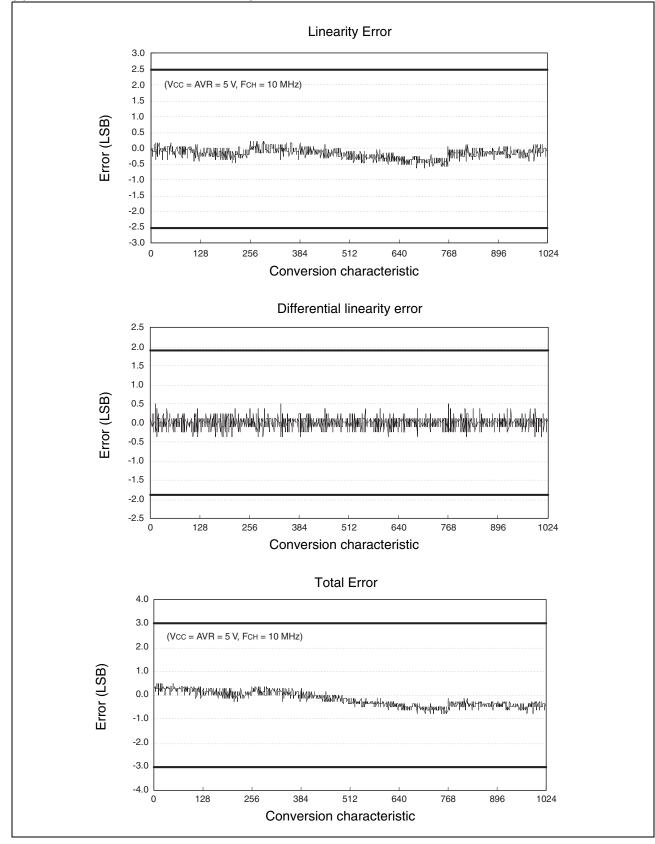
(5) "H" Level Output Voltage



(6) "L" Level Output Voltage



(7) AD Converter Characteristic Example



■ MASK OPTIONS

No	Part number	MB89535A MB89537A MB89537AC MB89538A MB89538AC	MB89F538-101 MB89F538-201	MB89P538-101 MB89P538-201	MB89PV530-101 MB89PV530-201
	Method of specification	Specify at time of mask order	Setting not possible	Setting not possible	Setting not possible
1	$\begin{array}{l} \mbox{Main clock} \\ \mbox{Select oscillator} \\ \mbox{stabilization wait period} \\ \mbox{(} F_{CH}^* = 10 \mbox{ MHz}) \\ \mbox{approx.2}^{14}/F_{CH}^* \\ \mbox{(} approx.1.6 \mbox{ ms}) \\ \mbox{approx.2}^{17}/F_{CH}^* \\ \mbox{(} approx.13.1 \mbox{ ms}) \\ \mbox{approx.2}^{18}/F_{CH}^* \\ \mbox{(} approx.26.2 \mbox{ ms}) \end{array}$	Selection available	2 ^{18/} F _{CH} * (approx. 26.2 ms)	2 ¹⁸ /F _{CH} * (approx. 26.2 ms)	2 ¹⁸ /F _{CH} * (approx. 26.2 ms)
2	Clock mode selection • 2-system clock mode • 1-system clock mode	Selection available	 101 : 1-system clock mode 201 : 2-system clock mode 		

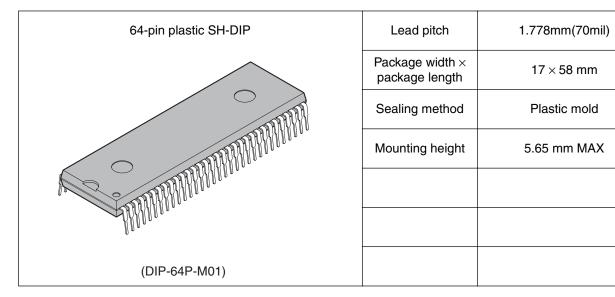
* : Fcн: Main clock frequency

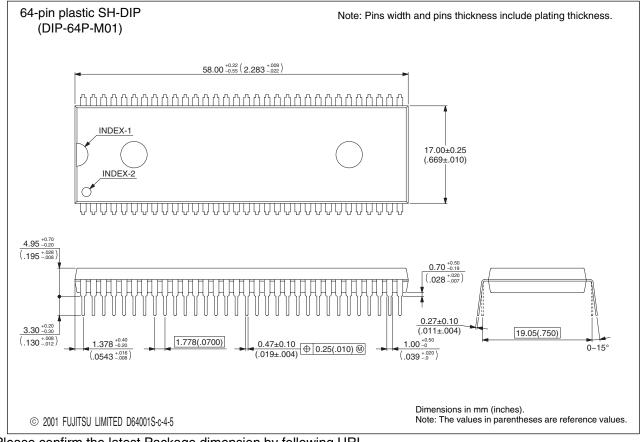
■ ORDERING INFORMATION

Part number	Package	Remarks
MB89535AP MB89537AP MB89537ACP MB89538AP MB89538ACP MB89P538P-101 MB89P538P-201 MB89F538P-101 MB89F538P-201	DIP-64P-M01	MB89535AP, MB89537AP and MB89538AP do not have I ² C functions.
MB89535APF MB89537APF MB89537ACPF MB89538APF MB89538ACPF MB89P538PF-101 MB89P538PF-201 MB89F538PF-101 MB89F538PF-201	FPT-64P-M06	MB89535APF, MB89537APF and MB89538APF do not have I ² C functions.
MB89535APFM MB89537APFM MB89537ACPFM MB89538APFM MB89538ACPFM MB89P538PFM-101 MB89P538PFM-201 MB89F538PFM-201 MB89F538PFM-201	FPT-64P-M09	MB89535APFM, MB89537APFM and MB89538APFM do not have I ² C functions.
MB89535APFV MB89537APFV MB89537ACPFV MB89538APFV MB89538ACPFV	FPT-64P-M03	MB89535APFV, MB89537APFV and MB89538APFV do not have I ² C functions.
MB89535APV4 MB89537APV4 MB89537ACPV4 MB89538APV4 MB89538ACPV4	LCC-64P-M19	MB89535APV4, MB89537APV4, and MB89538APV4 do not have I ² C functions.
MB89P538-101PV* MB89P538-201PV*	LCC-64P-M16*	
MB89PV530C-101 MB89PV530C-201	MDP-64C-P02	
MB89PV530CF-101 MB89PV530CF-201	MQP-64C-P01	

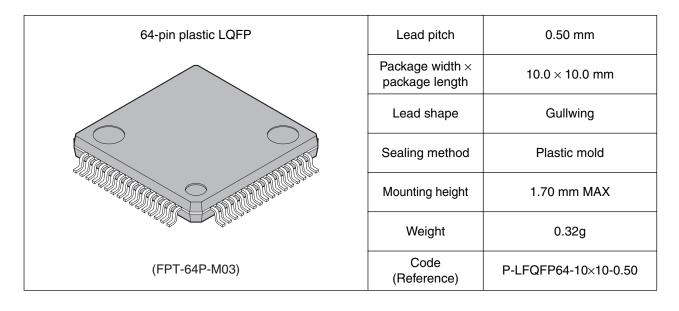
* : Only for ES

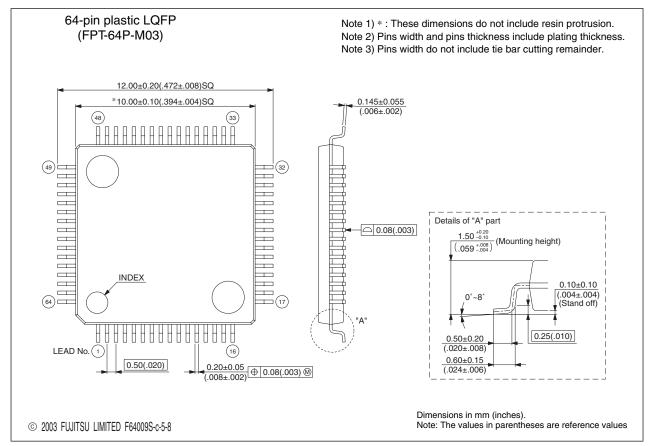
PACKAGE DIMENSIONS



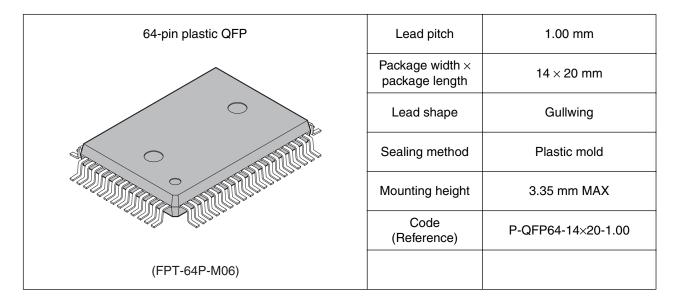


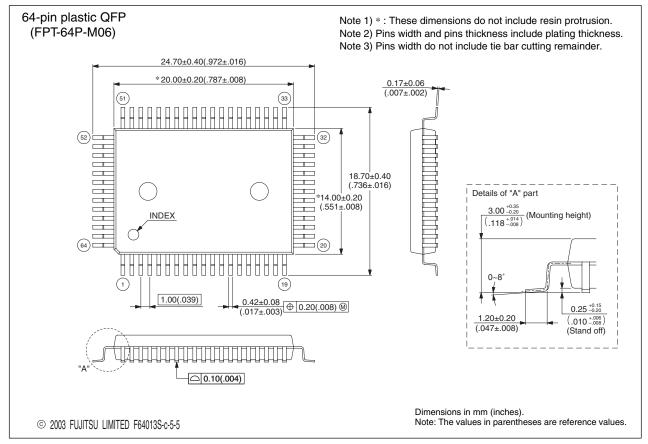
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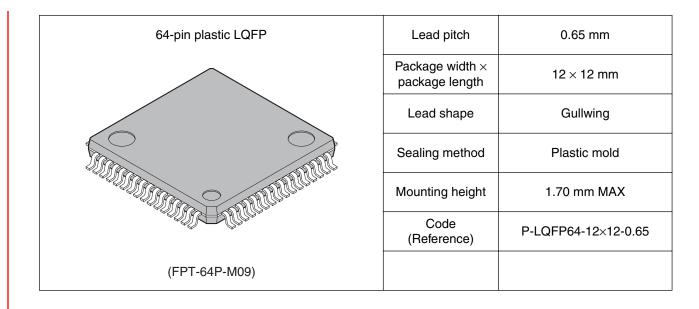


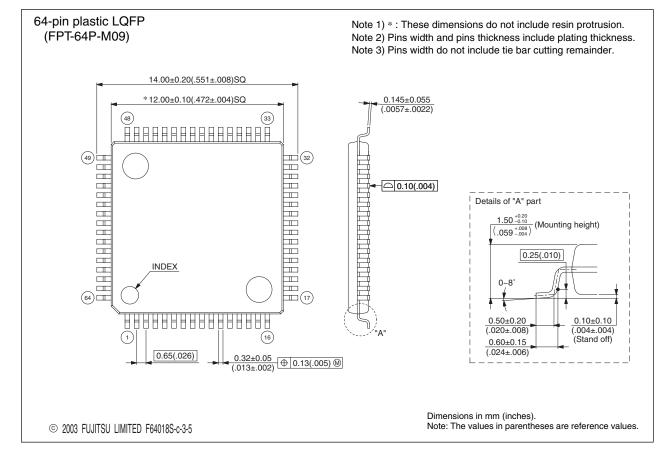
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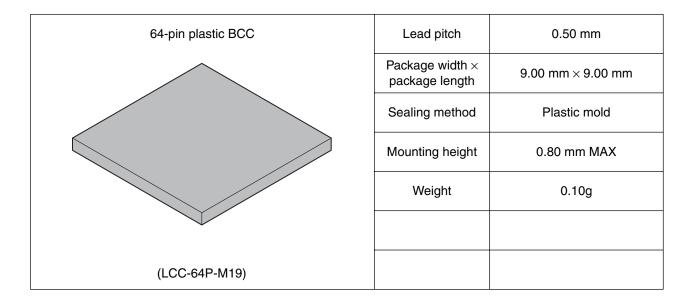


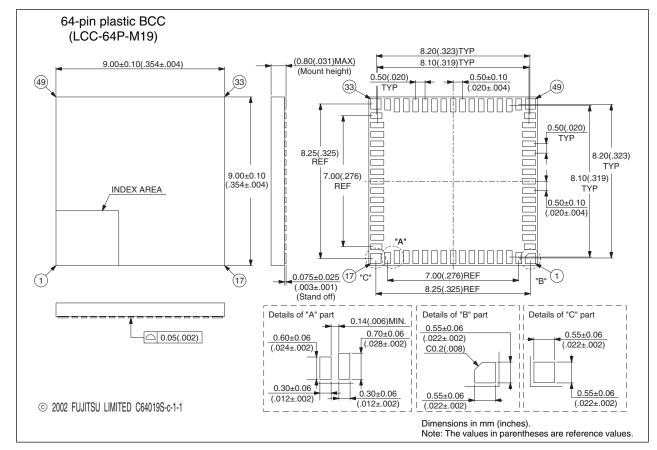
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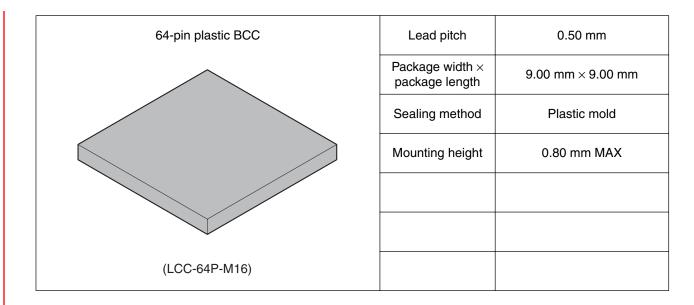


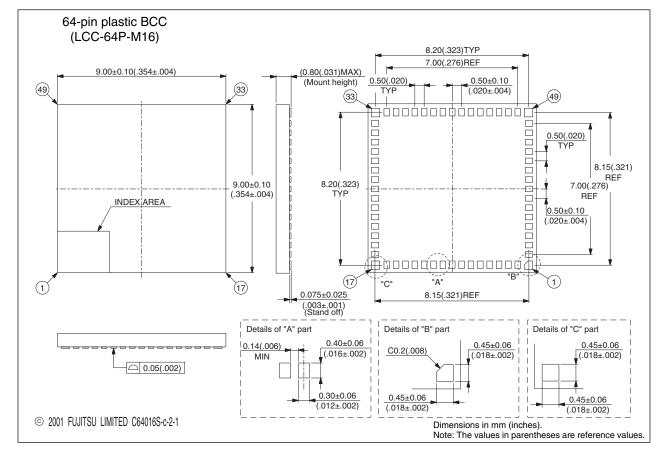
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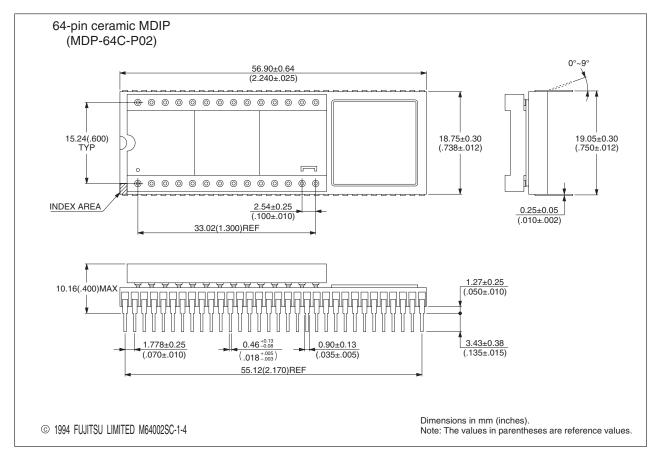
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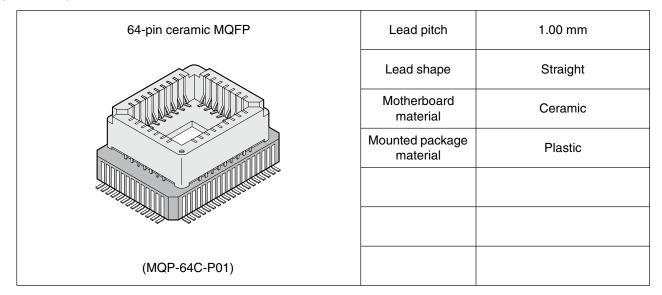


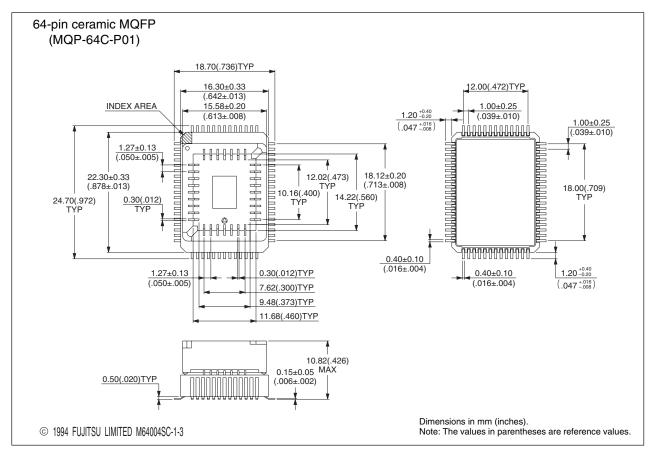
Please confirm the latest Package dimension by following URL. http://edevice.fujitsu.com/fj/DATASHEET/ef-ovpklv.html

64-pin ceramic MDIP	Lead pitch	70mil (1.778mm)
	Row spacing	750mil (15.24mm)
63030 000 000 000 000 000 000 000 000 00	Motherboard material	Ceramic
	Mounted packing material	Plastic
(MDP-64C-P02)		



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■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results
1	 FEATURES Wide range of package options 	Changes are as follows : • Two types of QFP packages (1 mm pitch, 0.65 mm pitch) • LQFP package (0.5 mm pitch) • SH-DIP package ↓ • QFP package (1.00 mm pitch) • Two types of LQFP packages (0.65 mm pitch, 0.50 mm pitch) • SH-DIP package (1.778 mm pitch) • BCC package (0.50 mm pitch)
2	 FEATURES External interrupt 2 	Changes are as follows : (8 channels) \rightarrow (except for MB89F538 : 8 channels, MB89F538 : 7 channels) 8 independent inputs \rightarrow 8 or 7 independent input
5	■ MODEL DIFFERENCES AND SELECTION	Added the rows of LCC-64P-M19 and LCC-64P-M16
	CONSIDERATIONS	Added the table footnote "* : Only for ES"
9	PIN ASSIGNMENTS	Changed the pins : P33/SI1 (U1) \rightarrow P33/SI1 (UI1)
10		Added the pin assignment for the LCC-64P-M19 and LCC-64P-M16
11 to 13	■ PIN DESCRIPTIONS	Changed the Pin no. : $QFP \rightarrow BCC$
13		For the function of MB89P538 in the pin name C, changes are as follows : Fixed at $V_{SS} \rightarrow$ If "Available" is selected for the step-down circuit stabilization time, V_{CC} is fixed. If "Unavailable" is selected for the step-down circuit stabilization time, V_{SS} is fixed.
		Changed the table footnote : * 5 : FPT-64P-M03 → * 5 : FPT-64P-M03/M09 * 6 : FPT-64P-M09 → * 6 : LCC-64P-M19/M16
18	 HANDLING DEVICES 9. Details on handling the C terminal of the MB89530 series 	Changed in the figure : ($2^{19}/Fch$) \rightarrow ($2^{19}/F_{CH}$) + ($2^{18}/F_{CH}$)
20	 PROGRAMMING AND ERASING FLASH MEMORY ON THE MB89F538 6. ROM Programmer Adaptor and Recommended ROM Programmers 	Changed in the Recommended Programmer Manufacturer and Model : Ando Electric Co. Ltd. \rightarrow Flash Support Group, Inc.
21	 ONE-TIME WRITING SPECIFICATIONS WITH PROM AND EPROM MICROCONTROLLERS ROM writer adapters 	Added the row of part number MB89P538-101PV, MB89P538-201PV Added "*2 : Only for ES"

(Continued)

Page	Section	Change Results
24	■ BLOCK DIAGRAM	Changed in the diagram : $X1 \leftrightarrow \rightarrow X1 \leftarrow$ 1KB RAM/2KB RAM \rightarrow RAM (512 Kbytes/1 Kbyte/2 Kbytes) 32KB ROM/48KB ROM \rightarrow ROM (16 Kbytes/32 Kbytes/48 Kbytes) MOD0, MOD1, C, Vcc, Vss \rightarrow MOD0, MOD1, MOD2*2, Vcc, Vss
31	■ I/O MAP	For the initial value with 7A, the change is as follows : $0~0~0~0~0~0$ - $0_B \rightarrow 0~0~0X0~0$ - 0_B
35	 ELECTRICAL CHARACTERISTICS Recommended Operating Conditions Operating voltage vs. operating frequency (MB89P538/MB89PV530) Operating voltage vs. operating frequency (MB89535A/537A/538A/537AC/538AC) 	Changed in the diagram : (at instruction cycle = $4/F_c$) \rightarrow (at instruction cycle = $4/F_{CH}$)
43	 ELECTRICAL CHARACTERISTICS 4. AC Characteristics 	Changed for the "Symbol" with "Input clock pulse width" : $P_{\text{WHH}} \rightarrow P_{\text{WHL}}$
44	(3) Clock Timing Standards	Changed in the X0A, X1A timing and application conditions : $P_{\text{WLH}} \rightarrow P_{\text{WHL}}$
		Added "Rd" in the Clock application conditions
56	 EXAMPLE CHARACTERISTICS (MB89538A) (7) AD Converter Characteristic Example 	Changed in the figure : Fc = 10 MHz \rightarrow FcH = 10 MHz
58	■ ORDERING INFORMATION	Added the rows of LCC-64P-M19 and LCC-64P-M16
		Added the "* : Only for ES"
62	■ PACKAGE DIMENSIONS	Changed the package name : 64-pin, Plastic QFP \rightarrow 64-pin plastic LQFP
63		Added the 64-pin, Plastic BCC (LCC-64P-M19)
64		Added the 64-pin, Plastic BCC (LCC-64P-M16)

The vertical lines marked in the left side of the page show the changes.

The information for microcontroller supports is shown in the following homepage. http://www.fujitsu.com/global/services/microelectronics/product/micom/support/index.html

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